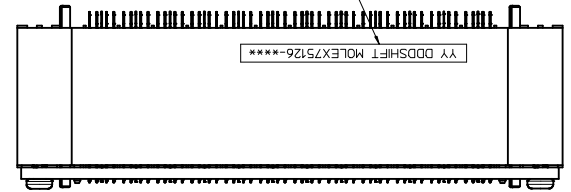


DATE CODE, MOLEX, PART NUMBER



NOTES:

1. MATERIALS FOR INTERPOSER AND HIGH SPEED DOCKING CONNECTOR:
HOUSING: LIQUID CRYSTAL POLYMER (LCP), GLASS FILLED, 94V-0.
WAFER DIELECTRIC: LIQUID CRYSTAL POLYMER (LCP), 94V-0, BLACK.
CONTACTS: COPPER ALLOY
HEXAGONAL MACHINE SCREW: CARBON STEEL
2. THIS ASSEMBLY CONFORMS TO PRODUCT SPECIFICATION PS-75018-001.
3. THIS ASSEMBLY TO BE PACKAGED PER PK-75126-001.
4. THIS ASSEMBLY CONFORMS TO CLASS C COSMETIC SPEC PS-45499-002.
5. RECOMMENDED DRILL SIZE: 0.61±0.03 TO YIELD FINISHED PLATED THROUGH HOLE OF 0.55±0.05.
6. USE APPLICATION TOOL 622020232 WHEN INSERTING INTO PCB.
7. RECOMMENDED SCREW LENGTH TO MOUNT TO PCB TO BE 5mm, PLUS MOTHER BOARD THICKNESS MIN. TORQUE REQUIREMENT: 2 IN-LBS MIN. 5 IN-LBS MAX.

CONVERT TO LEAD-FREE IEC NO: UCP2013-1884 DRAWN BY: IBARRA CHYK: APPR: MILLER 2012/11/12 2013/01/04	QUALITY SYMBOLS	GENERAL TOLERANCES (UNLESS SPECIFIED)	DIMENSION STYLE	SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION
	▽=0	mm INCH	MM/IN	2:1	METRIC	
	▽=0	4 PLACES ± --- ± ---	DATE	TITLE		
	▽=0	3 PLACES ± --- ± .010	02/06/27	PLATEAU HS DOCK INTERPOSER SALES DRAWING		
	2 PLACES ± 0.25 ± ---	DATE	DATE			
	1 PLACE ± --- ± ---	DATE	DATE			
	0 PLACE ± ±	DATE	DATE			
	ANGULAR ± 2 °	MATERIAL NO.	DOCUMENT NO.			SHEET NO.
	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	SEE TABLE	SD-75126-001			1 OF 3
		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION				

CIRCUIT SIZE	ITEM NUMBER	HS DOCK CONNECTOR	DIM 'A'	DIM 'B'	DIM 'C'	DIM 'D'	DIM 'E'	DIM 'F'	DIM 'G'	PLATING OPTION	CONNECTOR WAFER TYPE
108			90.50 3.563	81.50 3.209	89.00 3.504	75.62 2.977	99.40 3.913	71.00±0.08 2.795±.003	66.00±0.08 2.598±.003	FINISH 1	WELDED
144	75126-1003	75018-3021	111.50 4.390	102.50 4.035	110.00 4.331	96.62 3.804	120.40 4.740	92.00±0.08 3.622±.003	87.00±0.08 3.425±.003		
144	75126-1103	75018-3121	111.50 4.390	102.50 4.035	110.00 4.331	96.62 3.804	120.40 4.740	92.00±0.08 3.622±.003	87.00±0.08 3.425±.003	FINISH 2	
144	75126-3003	75018-3121	111.50 4.390	102.50 4.035	110.00 4.331	96.62 3.804	120.40 4.740	92.00±0.08 3.622±.003	87.00±0.08 3.425±.003		
144	75126-7103	75018-8121	111.50 4.390	102.50 4.035	110.00 4.331	96.62 3.804	120.40 4.740	92.00±0.08 3.622±.003	87.00±0.08 3.425±.003	FINISH 3	

1. PLATING FINISH:

FINISH 1: (PREVIOUSLY TIN-LEAD)

CONTACT INTERFACE

0.76 MICROMETERS/30 MICROINCHES MINIMUM SELECT GOLD

NICKEL UNDERPLATE OVERALL

COMPLIANT INTERFACE

0.76 MICROMETERS/30 MICROINCHES MINIMUM SELECT MATTE-TIN OVER

NICKEL UNDERPLATE OVERALL

HOUSING

0.10 MICROMETERS/4 MICROINCHES MAXIMUM GOLD OVER

3.81 MICROMETERS/150 MICROINCHES MINIMUM NICKEL OVER

COPPER UNDERPLATE OVERALL

FINISH 2:

CONTACT INTERFACE

0.76 MICROMETERS/30 MICROINCHES MINIMUM SELECT GOLD

NICKEL UNDERPLATE OVERALL

COMPLIANT INTERFACE

0.76 MICROMETERS/30 MICROINCHES MINIMUM SELECT MATTE-TIN OVER

NICKEL UNDERPLATE OVERALL

HOUSING

0.10 MICROMETERS/4 MICROINCHES MAXIMUM GOLD OVER

3.81 MICROMETERS/150 MICROINCHES MINIMUM NICKEL OVER

COPPER UNDERPLATE OVERALL

FINISH 3:

CONTACT INTERFACE

0.76 MICROMETERS/30 MICROINCHES MINIMUM SELECT GOLD

NICKEL UNDERPLATE OVERALL

COMPLIANT INTERFACE

0.76 MICROMETERS/30 MICROINCHES MINIMUM SELECT MATTE-TIN OVER

NICKEL UNDERPLATE OVERALL

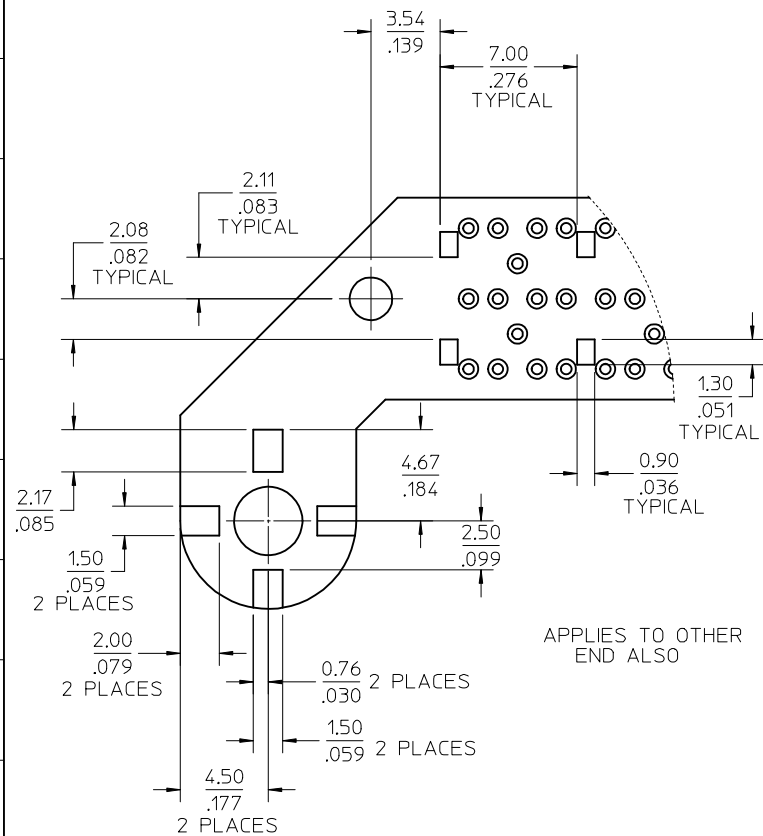
HOUSING

3.81 MICROMETERS/150 MICROINCHES MINIMUM NICKEL OVER

COPPER UNDERPLATE OVERALL

SEE SHEET 1 EC NO: UCP2013-1884 DRAWN BY: JORDWNTIBARRA CHKD: APPRS: MILLER 2012/11/12 2013/01/04	QUALITY SYMBOLS	GENERAL TOLERANCES (UNLESS SPECIFIED)	DIMENSION STYLE	SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION
	▽=0	4 PLACES ±.010	MM/IN	2:1	METRIC	
	▽=0	3 PLACES ±.010				
	▽=0	2 PLACES ±0.25				
		1 PLACE ±.010				
		0 PLACE ±.010				
		ANGULAR ± 2 °				
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS				
			DRAWN BY: DSCHMIDG	DATE: 02/06/27	TITLE: PLATEAU HS DOCK INTERPOSER SALES DRAWING	
			CHECKED BY: DSCHMIDG	DATE: 2003/03/18		
			APPROVED BY: MBANKIS	DATE: 2/18/03		
			MATERIAL NO. SEE TABLE	DOCUMENT NO. SD-75126-001	SHEET NO. 2 OF 3	
			THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			

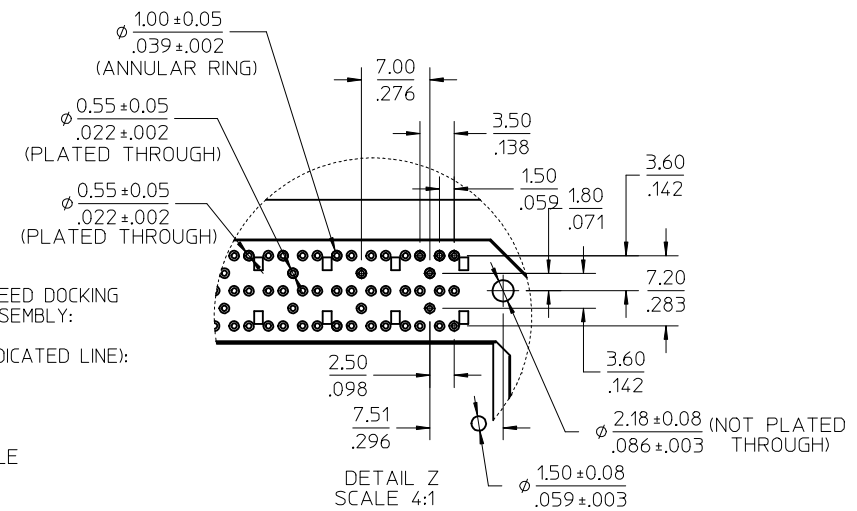
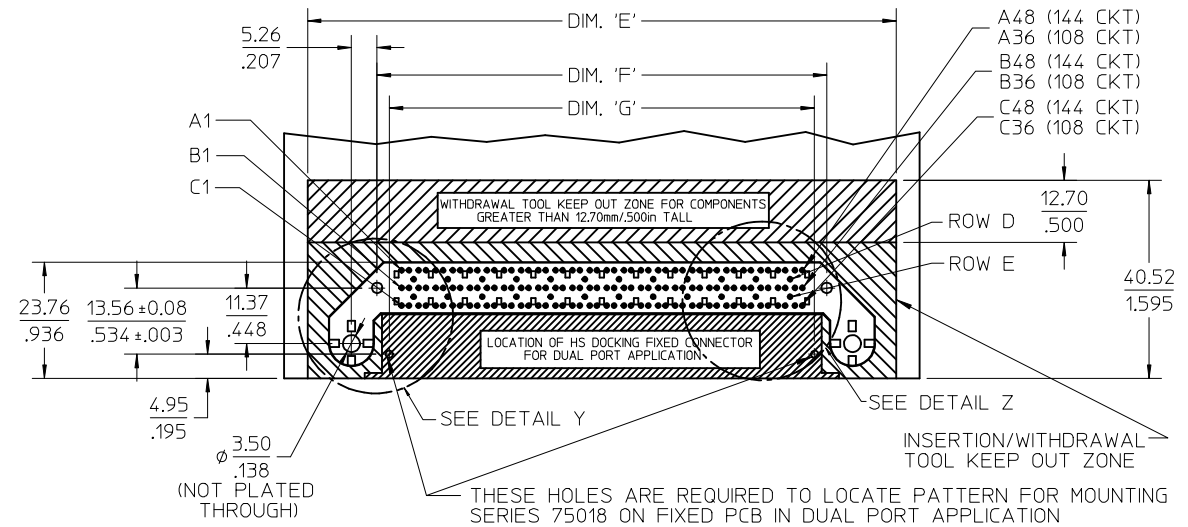
KEEP OUT AREA FOR CONNECTOR STAND-OFFS



DETAIL Y
SCALE 8:1

NOTE: THE DIMENSION DEFINING THE LOCATION AND SIZE OF THE KEEP OUT AREAS DO NOT HAVE TOLERANCES. AT A MINIMUM THE POWER PLANE MUST NOT COME INSIDE THE AREAS DEFINED BY THESE DIMENSIONS.

APPLIES TO OTHER END ALSO

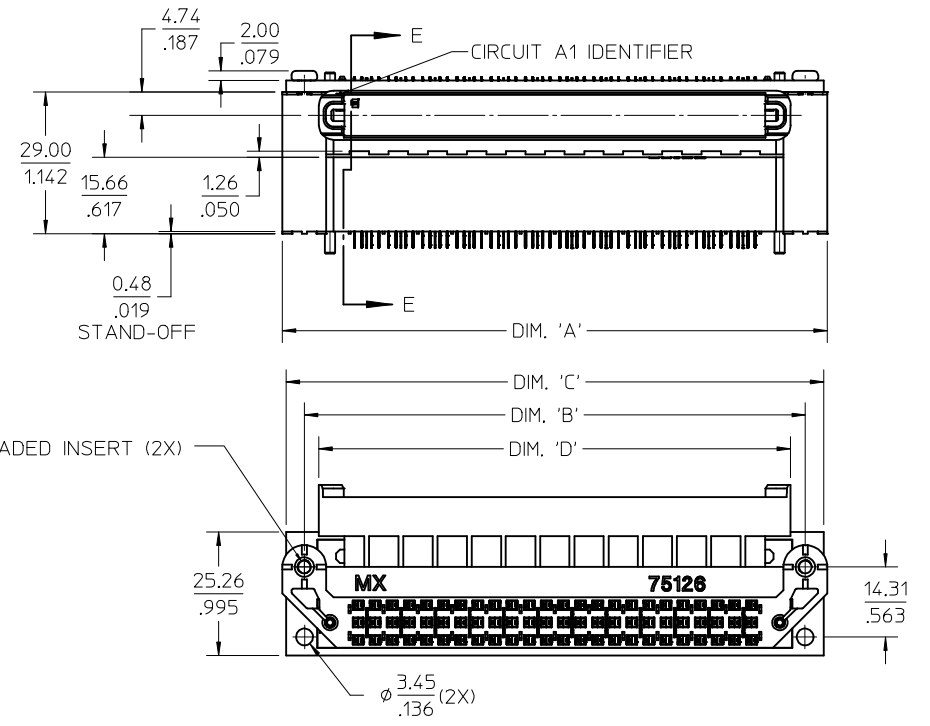
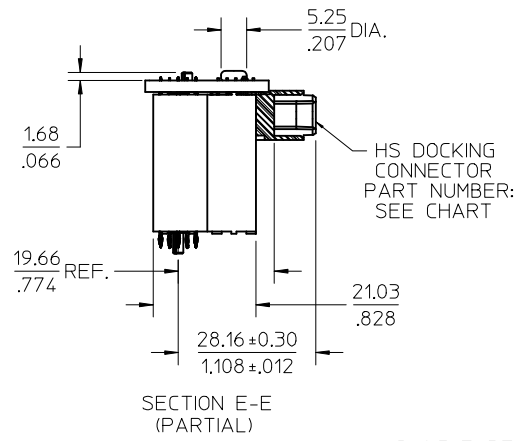
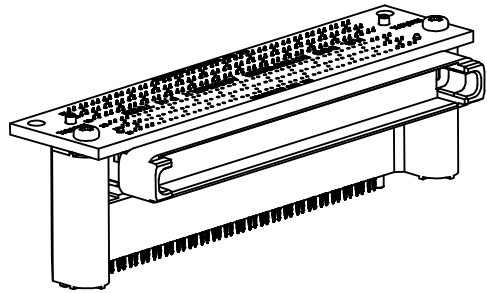


CIRCUIT DESIGNATION FOR HIGH SPEED DOCKING INTERPOSER CONNECTOR ASSEMBLY:
 A2-A1: POWER/RETURN;
 A4-A3: POWER/RETURN;
 C2-C1: POWER/RETURN

POWER CIRCUITS (15 AMPS PER INDICATED LINE):
 ALL REMAINING ROWS ARE SUITABLE FOR DIFFERENTIAL PAIRS
 CURRENT CAPACITY: 300mA

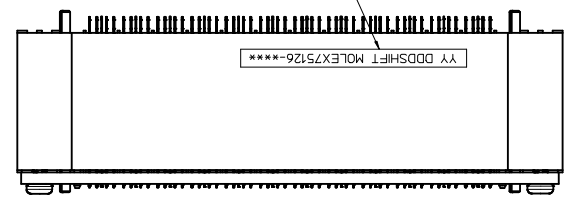
GROUND CIRCUITS: ROWS D & E

SEE SHEET 1 IEC NO: UCP2013-1884 DRAWN: IBARRA 2012/11/12 CHKO: APPROV: SMILLER 2013/01/04	QUALITY SYMBOLS	GENERAL TOLERANCES (UNLESS SPECIFIED)	DIMENSION STYLE	SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION
	▽=0	mm INCH	MM/IN	1:1	METRIC	☉
	▽=0	4 PLACES ± --- ± ---	DRAWN BY DATE	TITLE		
	▽=0	3 PLACES ± --- ± .010	DSCMIDG 02/06/127	PLATEAU HS DOCK INTERPOSER SALES DRAWING		
	2 PLACES ± 0.25 ± ---	CHECKED BY DATE	DOCUMENT NO.			
	1 PLACE ± --- ± ---	DSCMIDG 2003/03/18	SD-75126-001			
	0 PLACE ± ±	APPROVED BY DATE	SHEET NO.			
		MBANKI S 2/18/03	3 OF 3			
		MATERIAL NO.	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			
		SEE TABLE				



M3x0.5 THREADED INSERT (2X)

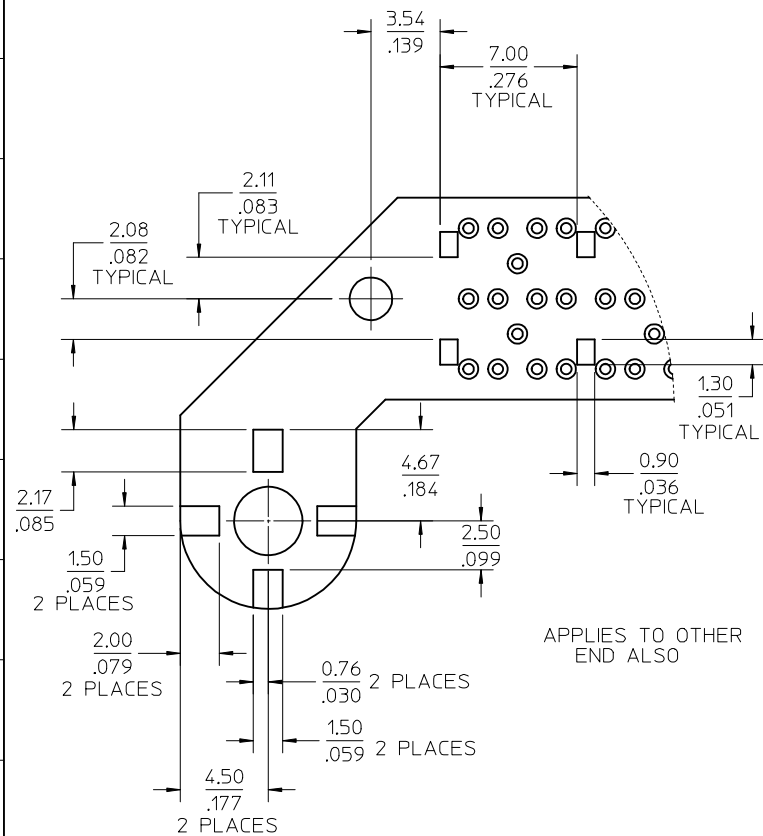
DATE CODE, MOLEX, PART NUMBER



- NOTES:
1. MATERIALS FOR INTERPOSER AND HIGH SPEED DOCKING CONNECTOR:
HOUSING: LIQUID CRYSTAL POLYMER (LCP), GLASS FILLED, 94V-0.
WAFER DIELECTRIC: LIQUID CRYSTAL POLYMER (LCP), 94V-0, BLACK.
CONTACTS: COPPER ALLOY
HEXAGONAL MACHINE SCREW: CARBON STEEL
 2. THIS ASSEMBLY CONFORMS TO PRODUCT SPECIFICATION PS-75018-001.
 3. THIS ASSEMBLY TO BE PACKAGED PER PK-75126-001.
 4. THIS ASSEMBLY CONFORMS TO CLASS C COSMETIC SPEC PS-45499-002.
 5. RECOMMENDED DRILL SIZE: 0.61±0.03 TO YIELD FINISHED PLATED THROUGH HOLE OF 0.55±0.05.
 6. USE APPLICATION TOOL 622020232 WHEN INSERTING INTO PCB.
 7. RECOMMENDED SCREW LENGTH TO MOUNT TO PCB TO BE 5mm, PLUS MOTHER BOARD THICKNESS MIN. TORQUE REQUIREMENT: 2 IN-LBS MIN. 5 IN-LBS MAX.

CONVERT TO LEAD-FREE IEC NO: UCP2013-1884 DRAWN: IBARRA 2012/11/12 CHKD: MILLER APPR: MILLER 2013/01/04 DESCRIPTION:	QUALITY SYMBOLS	GENERAL TOLERANCES (UNLESS SPECIFIED)	DIMENSION STYLE	SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION
	▽=0	mm INCH	MM/IN	2:1	METRIC	
	▽=0	4 PLACES ± --- ± ---	DATE	TITLE		
	▽=0	3 PLACES ± --- ± .010	02/06/27	PLATEAU HS DOCK INTERPOSER SALES DRAWING		
	2 PLACES ± 0.25 ± ---	DATE	DATE			
	1 PLACE ± --- ± ---	DATE	DATE			
	0 PLACE ± ±	DATE	DATE			
	ANGULAR ± 2 °	MATERIAL NO.	DOCUMENT NO.			SHEET NO.
	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	SEE TABLE	SD-75126-001			1 OF 3
		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION				

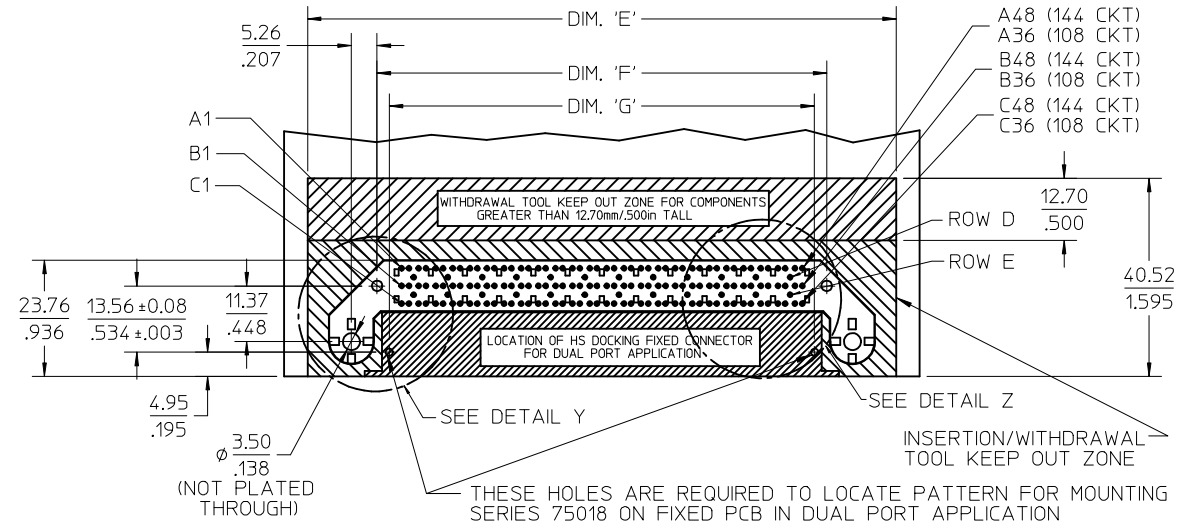
KEEP OUT AREA FOR CONNECTOR STAND-OFFS



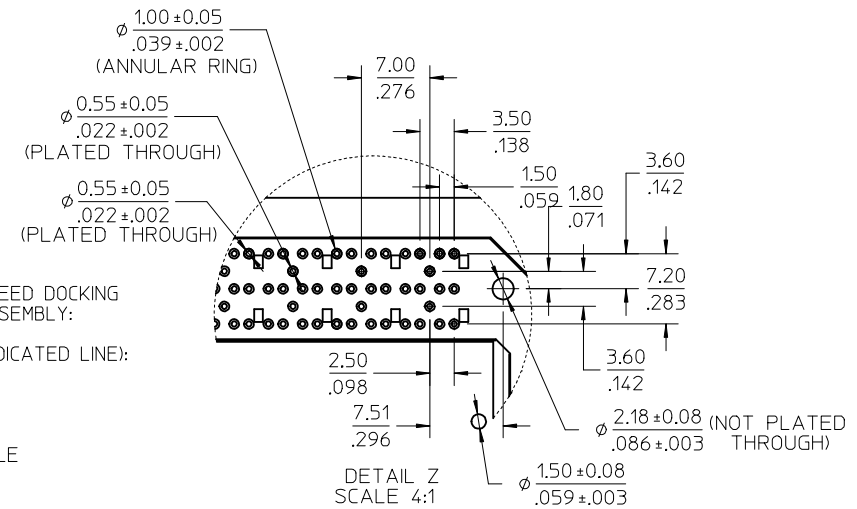
DETAIL Y
SCALE 8:1

NOTE: THE DIMENSION DEFINING THE LOCATION AND SIZE OF THE KEEP OUT AREAS DO NOT HAVE TOLERANCES. AT A MINIMUM THE POWER PLANE MUST NOT COME INSIDE THE AREAS DEFINED BY THESE DIMENSIONS.

APPLIES TO OTHER END ALSO



THESE HOLES ARE REQUIRED TO LOCATE PATTERN FOR MOUNTING SERIES 75018 ON FIXED PCB IN DUAL PORT APPLICATION



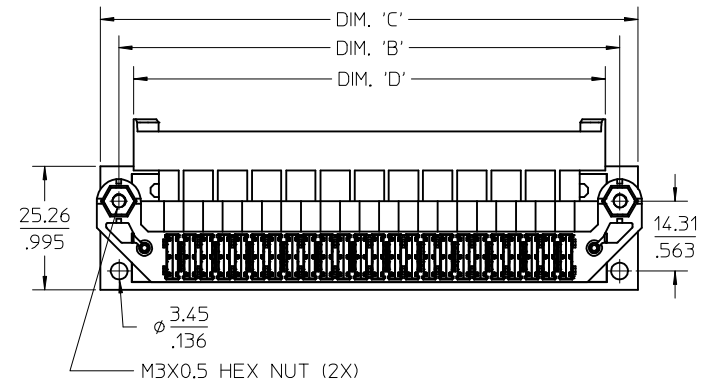
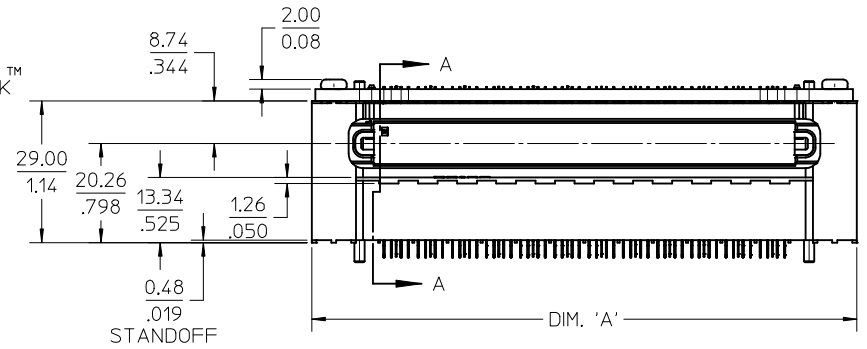
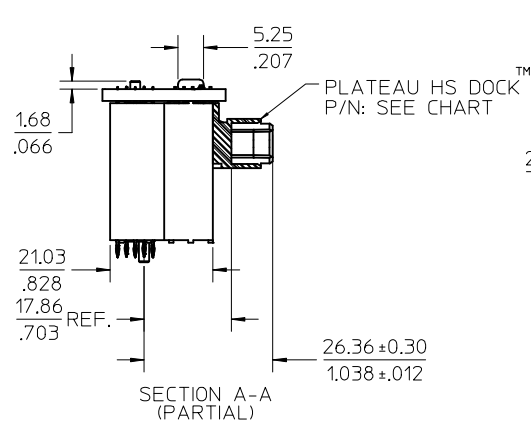
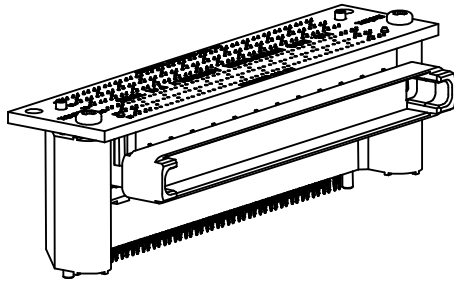
CIRCUIT DESIGNATION FOR HIGH SPEED DOCKING INTERPOSER CONNECTOR ASSEMBLY:

POWER CIRCUITS (15 AMPS PER INDICATED LINE):
A2-A1: POWER/RETURN;
A4-A3: POWER/RETURN;
C2-C1: POWER/RETURN

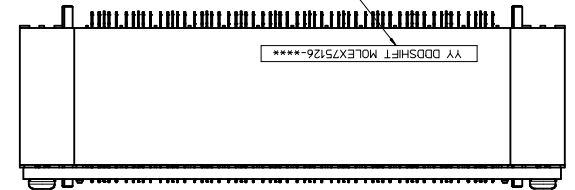
ALL REMAINING ROWS ARE SUITABLE FOR DIFFERENTIAL PAIRS
CURRENT CAPACITY: 300mA

GROUND CIRCUITS: ROWS D & E

SEE SHEET 1 EC NO: UCP2013-1884 DRAWN: IBARRA 2012/11/12 CHKD: APPR: SKILLER 2013/01/04	QUALITY SYMBOLS	GENERAL TOLERANCES (UNLESS SPECIFIED)	DIMENSION STYLE	SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION
	▽=0	mm INCH	MM/IN	1:1	METRIC	☉
	▽=0	4 PLACES ± --- ± ---	DRAWN BY DATE	TITLE		
	▽=0	3 PLACES ± --- ± .010	DSCMIDG 02/06/12	PLATEAU HS DOCK INTERPOSER SALES DRAWING		
	2 PLACES ± 0.25 ± ---	CHECKED BY DATE	DOCUMENT NO.			
	1 PLACE ± --- ± ---	DSCMIDG 2003/03/18	SD-75126-001			
	0 PLACE ± ±	APPROVED BY DATE	SHEET NO.			
		MBANKIS 2/18/03	3 OF 3			
		MATERIAL NO.	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			
		SEE TABLE				



DATE CODE, MOLEX, PART NUMBER



NOTES:

1. MATERIALS FOR INTERPOSER AND HIGH SPEED DOCKING CONNECTOR:
HOUSING: LIQUID CRYSTAL POLYMER (LCP), GLASS FILLED, 94 V-0.
WAFER: LIQUID CRYSTAL POLYMER (LCP), 94 V-0, BLACK.
CONTACTS: COPPER ALLOY
HEXAGONAL THREADED INSERT: CARBON STEEL
MACHINE SCREW: CARBON STEEL
2. THIS ASSEMBLY CONFORMS TO PRODUCT SPECIFICATION PS-75018-001.
3. THIS ASSEMBLY TO BE PACKAGED PER PK-75126-001.
4. THIS ASSEMBLY CONFORMS TO CLASS C COSMETIC SPEC. PS-45499-002.
5. RECOMMENDED DRILL SIZE: 0.66±0.03 TO YIELD FINISHED PLATED THROUGH HOLE OF 0.55±0.05.
6. USE APPLICATION TOOL 62202XXXX WHEN INSERTING INTO PCB.
7. RECOMMENDED SCREW LENGTH TO MOUNT TO PCB TO BE 5mm, PLUS MOTHER BOARD THCKNESS MIN. TORQUE REQUIREMENT: 2 IN-LBS MIN. 5 IN-LBS MAX.

CONVERT TO LEAD-FREE EC NO: UCP2013-1884 2012/11/12 DRAWN BY: J BARRA CHKD: J BARRA APPR: MILLER 2013/01/04	QUALITY SYMBOLS	GENERAL TOLERANCES (UNLESS SPECIFIED)	DIMENSION STYLE	SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION
	▽=0	mm INCH	MM/IN	2:1	METRIC	☉
	▽=0	4 PLACES ± --- ± --- 3 PLACES ± --- ± .010 2 PLACES ± 0.25 ± --- 1 PLACE ± --- ± --- 0 PLACE ± ±	DRAWN BY: KSTILES DATE: 7/16/2003 CHECKED BY: DATE: 7/16/2003 DSCM1DG APPROVED BY: DATE: 7/16/2003 MBANKIS	TITLE	PLATEAU HS DOCK 8.74 CL INTERPOSER SALES DRAWING	
	▽=0	ANGULAR ±1/2° DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	SEE TABLE	DOCUMENT NO.	SD-75126-002 SHEET NO. 1 OF 3	
MATERIAL NO. SD-75126-002 SIZE D THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION						

CIRCUIT SIZE	ITEM NUMBER	PLATEAU HS DOCK™	DIM 'A'	DIM 'B'	DIM 'C'	DIM 'D'	DIM 'E'	DIM 'F'	DIM 'G'	PLATING FINISH	CONNECTOR WAFER TYPE	
108			90.50 3.563	81.50 3.209	89.00 3.504	75.62 2.977	99.40 3.913	71.00±0.08 2.795±.003	66.00±0.08 2.598±.003	FINISH 1	WELDED	
144	75126-2001	75018-3023	111.50 4.390	102.50 4.035	110.00 4.331	96.62 3.804	120.40 4.740	92.00±0.08 3.622±.003	87.00±0.08 3.425±.003			
144	75126-2101	75018-3123	111.50 4.390	102.50 4.035	110.00 4.331	96.62 3.804	120.40 4.740	92.00±0.08 3.622±.003	87.00±0.08 3.425±.003	FINISH 2		
144	75126-4001	75018-3123	111.50 4.390	102.50 4.035	110.00 4.331	96.62 3.804	120.40 4.740	92.00±0.08 3.622±.003	87.00±0.08 3.425±.003			
144	75126-8101	75018-8123	111.50 4.390	102.50 4.035	110.00 4.331	96.62 3.804	120.40 4.740	92.00±0.08 3.622±.003	87.00±0.08 3.425±.003	FINISH 3		WELDLESS

1. PLATING FINISH:

FINISH 1: (PREVIOUSLY TIN-LEAD)

CONTACT INTERFACE

0.76 MICROMETERS/30 MICROINCHES MINIMUM SELECT GOLD
NICKEL UNDERPLATE OVERALL

COMPLIANT INTERFACE

0.76 MICROMETERS/30 MICROINCHES MINIMUM SELECT MATTE-TIN OVER
NICKEL UNDERPLATE OVERALL

HOUSING

0.10 MICROMETERS/4 MICROINCHES MAXIMUM GOLD OVER
3.81 MICROMETERS/150 MICROINCHES MINIMUM NICKEL OVER
COPPER UNDERPLATE OVERALL

FINISH 2:

CONTACT INTERFACE

0.76 MICROMETERS/30 MICROINCHES MINIMUM SELECT GOLD
NICKEL UNDERPLATE OVERALL

COMPLIANT INTERFACE

0.76 MICROMETERS/30 MICROINCHES MINIMUM SELECT MATTE-TIN OVER
NICKEL UNDERPLATE OVERALL

HOUSING

0.10 MICROMETERS/4 MICROINCHES MAXIMUM GOLD OVER
3.81 MICROMETERS/150 MICROINCHES MINIMUM NICKEL OVER
COPPER UNDERPLATE OVERALL

FINISH 3:

CONTACT INTERFACE

0.76 MICROMETERS/30 MICROINCHES MINIMUM SELECT GOLD
NICKEL UNDERPLATE OVERALL

COMPLIANT INTERFACE

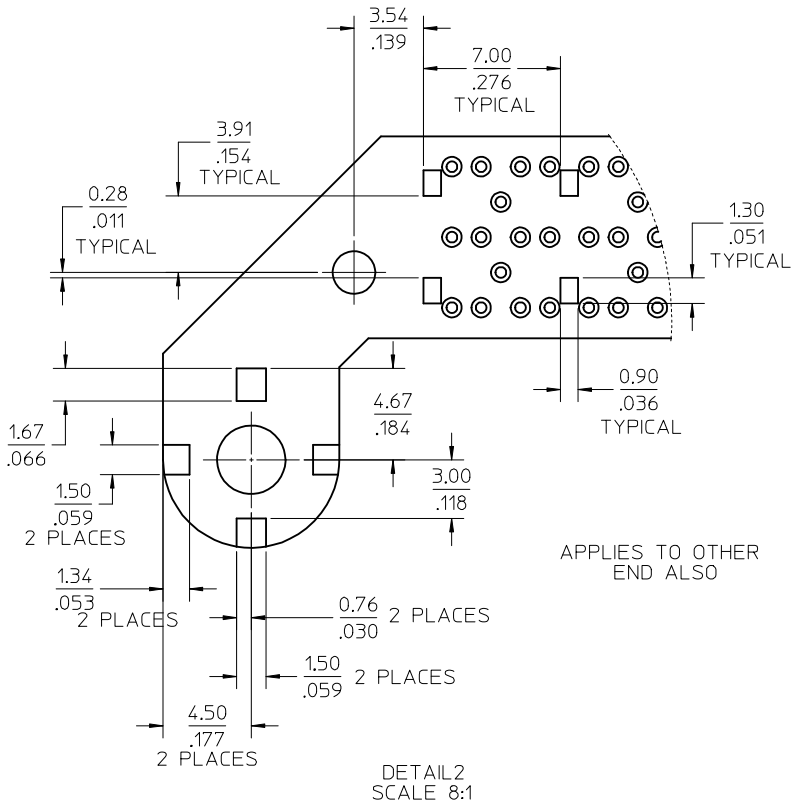
0.76 MICROMETERS/30 MICROINCHES MINIMUM SELECT MATTE-TIN OVER
NICKEL UNDERPLATE OVERALL

HOUSING

3.81 MICROMETERS/150 MICROINCHES MINIMUM NICKEL OVER
COPPER UNDERPLATE OVERALL

SEE SHEET 1 EC NO: UCP2013-1884 DRAWN BY: J. BARRA CHKD: J. BARRA APPR: MILLER 2012/11/12 2013/01/04	QUALITY SYMBOLS	GENERAL TOLERANCES (UNLESS SPECIFIED)	DIMENSION STYLE	SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION
	▽=0	4 PLACES ±.010	MM/IN	2:1	METRIC	
	▽=0	3 PLACES ±.025				
	▽=0	2 PLACES ±.050				
		ANGULAR ±1/2°	DRAWN BY: KSTILES	DATE: 7/16/2003	TITLE: PLATEAU HS DOCK 8.74 CL INTERPOSER SALES DRAWING	
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	CHECKED BY: DSCHMIDG	DATE: 7/16/2003	molex	
			APPROVED BY: MBANKIS	DATE: 7/16/2003	DOCUMENT NO. SD-75126-002	
			MATERIAL NO.	DATE: 7/16/2003	SHEET NO. 2 OF 3	
			SIZE: D		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION	

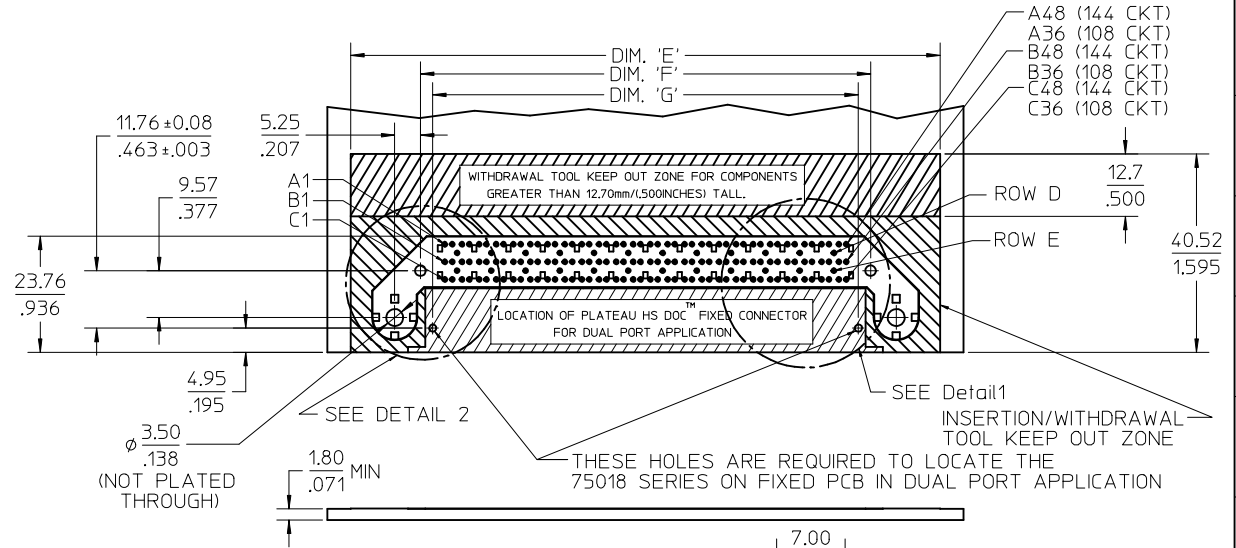
KEEP OUT AREA FOR STAND-OFFS



DETAIL2
SCALE 8:1

NOTE: THE DIMENSIONS DEFINING THE LOCATION AND SIZE OF THE KEEP OUT AREAS DO NOT HAVE TOLERANCES. AT A MINIMUM THE POWER PLANE MUST NOT COME INSIDE THE AREAS DEFINED BY THESE DIMENSIONS.

APPLIES TO OTHER END ALSO

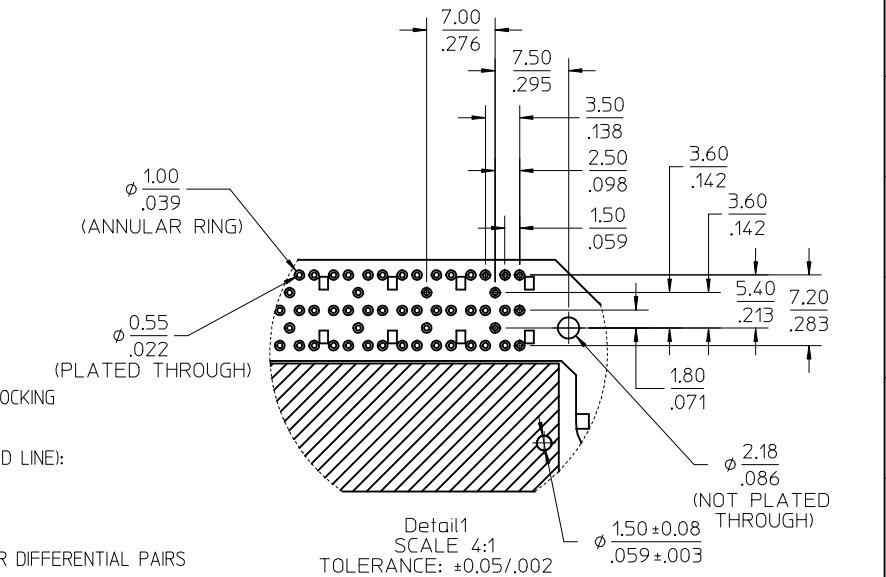


CIRCUIT DESIGNATION FOR HIGH SPEED DOCKING INTERPOSER CONNECTOR ASSEMBLY:

POWER CIRCUITS (15 AMPS PER INDICATED LINE):
A2-A1: POWER/RETURN,
A4-A3: POWER/RETURN,
C2-C1: POWER/RETURN

ALL REMAINING ROWS ARE SUITABLE FOR DIFFERENTIAL PAIRS
CURRENT CAPACITY: 300ma

GROUND CIRCUITS: ROWS D & E



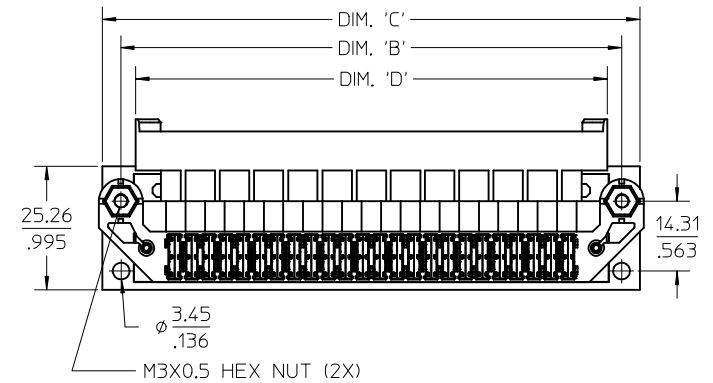
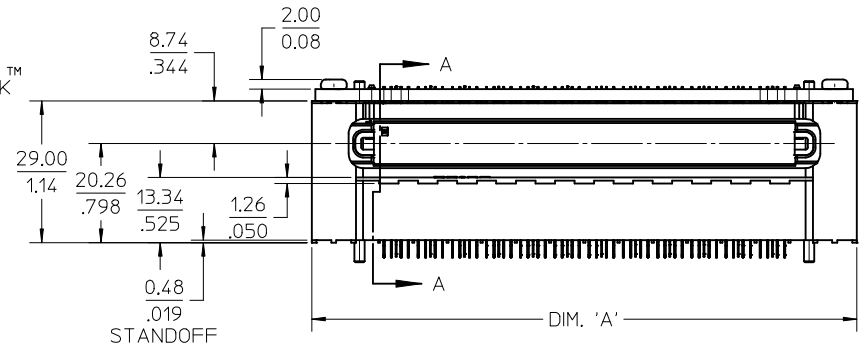
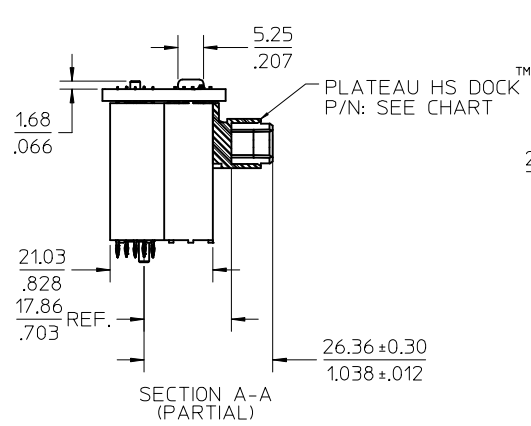
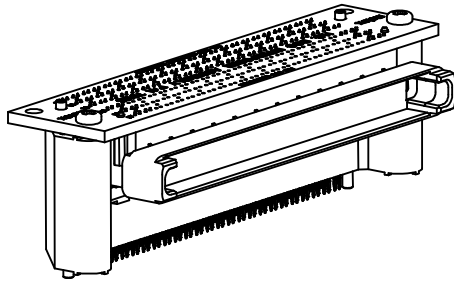
Detail1
SCALE 4:1

TOLERANCE: ±0.05/.002

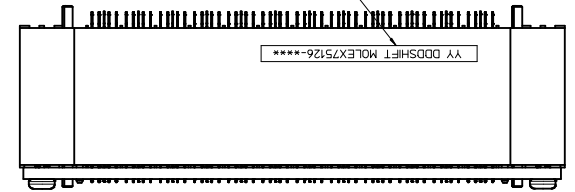
SEE SHEET 1 IEC NO: UCP2013-1884 DRAWN: TIBARRA 2012/11/12 CHKD: APPROV: SMILLER 2013/01/04 DESCRIPTION	QUALITY SYMBOLS	GENERAL TOLERANCES (UNLESS SPECIFIED)	DIMENSION STYLE	SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION
	▽=0	mm INCH	MM/IN	2:1	METRIC	☉
	▽=0	4 PLACES ± .010	DRAWN BY DATE			
	▽=0	3 PLACES ± .025	CHECKED BY DATE			
		1 PLACE ± .010	DSCM1DG 7/16/2003			
		0 PLACE ± .010	APPROVED BY DATE			
			MBANKIS 7/16/2003			
		ANGULAR ±1/2°	MATERIAL NO.			
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	SEE TABLE			
			DOCUMENT NO.			
			SD-75126-002			
			SHEET NO.			
			3 OF 3			

PLATEAU HS DOCK
8.74 CL INTERPOSER
SALES DRAWING
molex

THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION



DATE CODE, MOLEX, PART NUMBER



NOTES:

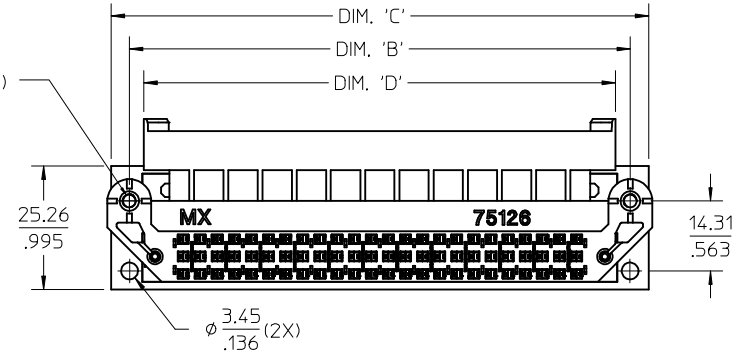
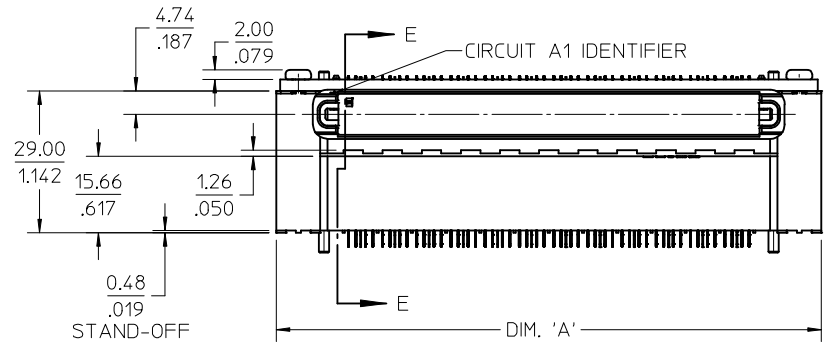
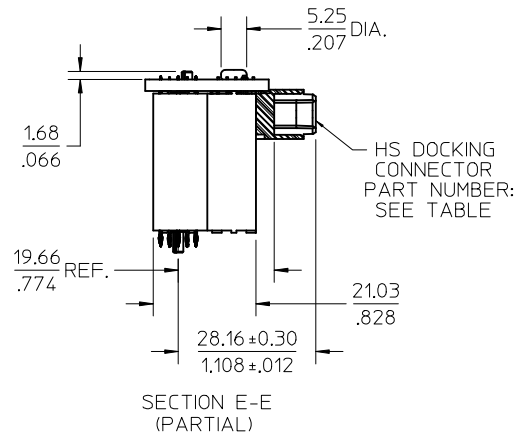
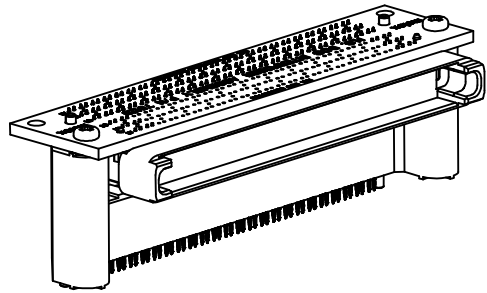
1. MATERIALS FOR INTERPOSER AND HIGH SPEED DOCKING CONNECTOR:
HOUSING: LIQUID CRYSTAL POLYMER (LCP), GLASS FILLED, 94 V-0.
WAFER: LIQUID CRYSTAL POLYMER (LCP), 94 V-0, BLACK.
CONTACTS: COPPER ALLOY
HEXAGONAL THREADED INSERT: CARBON STEEL
MACHINE SCREW: CARBON STEEL
2. THIS ASSEMBLY CONFORMS TO PRODUCT SPECIFICATION PS-75018-001.
3. THIS ASSEMBLY TO BE PACKAGED PER PK-75126-001.
4. THIS ASSEMBLY CONFORMS TO CLASS C COSMETIC SPEC. PS-45499-002.
5. RECOMMENDED DRILL SIZE: 0.66±0.03 TO YIELD FINISHED PLATED THROUGH HOLE OF 0.55±0.05.
6. USE APPLICATION TOOL 62202XXXX WHEN INSERTING INTO PCB.
7. RECOMMENDED SCREW LENGTH TO MOUNT TO PCB TO BE 5mm, PLUS MOTHER BOARD THCKNESS MIN. TORQUE REQUIREMENT: 2 IN-LBS MIN. 5 IN-LBS MAX.

CONVERT TO LEAD-FREE EC NO: UCP2013-1884 2012/11/12 DRAWN BY: J BARRA CHKD: J BARRA APPR: MILLER 2013/01/04	QUALITY SYMBOLS	GENERAL TOLERANCES (UNLESS SPECIFIED)	DIMENSION STYLE	SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION
	▽=0	mm INCH	MM/IN	2:1	METRIC	☉
	▽=0	4 PLACES ± --- ± --- 3 PLACES ± --- ± .010 2 PLACES ± 0.25 ± --- 1 PLACE ± --- ± --- 0 PLACE ± ±	DRAWN BY: KSTILES DATE: 7/16/2003 CHECKED BY: DATE: 7/16/2003 DSCM1DG APPROVED BY: DATE: 7/16/2003 MBANKIS	TITLE	PLATEAU HS DOCK 8.74 CL INTERPOSER SALES DRAWING	
	▽=0	ANGULAR ±1/2° DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	SEE TABLE	DOCUMENT NO.	SD-75126-002 SHEET NO. 1 OF 3	
MATERIAL NO. SD-75126-002 SIZE D THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION						

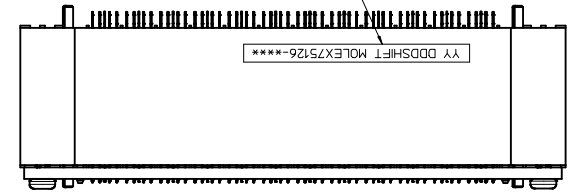
CIRCUIT SIZE	ITEM NUMBER	PLATEAU HS DOCK™	DIM 'A'	DIM 'B'	DIM 'C'	DIM 'D'	DIM 'E'	DIM 'F'	DIM 'G'	PLATING FINISH	CONNECTOR WAFER TYPE
108			90.50 3.563	81.50 3.209	89.00 3.504	75.62 2.977	99.40 3.913	71.00±0.08 2.795±.003	66.00±0.08 2.598±.003	FINISH 1	WELDED
144	75126-2001	75018-3023	111.50 4.390	102.50 4.035	110.00 4.331	96.62 3.804	120.40 4.740	92.00±0.08 3.622±.003	87.00±0.08 3.425±.003		
144	75126-2101	75018-3123	111.50 4.390	102.50 4.035	110.00 4.331	96.62 3.804	120.40 4.740	92.00±0.08 3.622±.003	87.00±0.08 3.425±.003	FINISH 2	
144	75126-4001	75018-3123	111.50 4.390	102.50 4.035	110.00 4.331	96.62 3.804	120.40 4.740	92.00±0.08 3.622±.003	87.00±0.08 3.425±.003		
144	75126-8101	75018-8123	111.50 4.390	102.50 4.035	110.00 4.331	96.62 3.804	120.40 4.740	92.00±0.08 3.622±.003	87.00±0.08 3.425±.003	FINISH 3	

1. PLATING FINISH:
- FINISH 1: (PREVIOUSLY TIN-LEAD)
 - CONTACT INTERFACE
 - 0.76 MICROMETERS/30 MICROINCHES MINIMUM SELECT GOLD
 - NICKEL UNDERPLATE OVERALL
 - COMPLIANT INTERFACE
 - 0.76 MICROMETERS/30 MICROINCHES MINIMUM SELECT MATTE-TIN OVER
 - NICKEL UNDERPLATE OVERALL
 - HOUSING
 - 0.10 MICROMETERS/4 MICROINCHES MAXIMUM GOLD OVER
 - 3.81 MICROMETERS/150 MICROINCHES MINIMUM NICKEL OVER
 - COPPER UNDERPLATE OVERALL
 - FINISH 2:
 - CONTACT INTERFACE
 - 0.76 MICROMETERS/30 MICROINCHES MINIMUM SELECT GOLD
 - NICKEL UNDERPLATE OVERALL
 - COMPLIANT INTERFACE
 - 0.76 MICROMETERS/30 MICROINCHES MINIMUM SELECT MATTE-TIN OVER
 - NICKEL UNDERPLATE OVERALL
 - HOUSING
 - 0.10 MICROMETERS/4 MICROINCHES MAXIMUM GOLD OVER
 - 3.81 MICROMETERS/150 MICROINCHES MINIMUM NICKEL OVER
 - COPPER UNDERPLATE OVERALL
 - FINISH 3:
 - CONTACT INTERFACE
 - 0.76 MICROMETERS/30 MICROINCHES MINIMUM SELECT GOLD
 - NICKEL UNDERPLATE OVERALL
 - COMPLIANT INTERFACE
 - 0.76 MICROMETERS/30 MICROINCHES MINIMUM SELECT MATTE-TIN OVER
 - NICKEL UNDERPLATE OVERALL
 - HOUSING
 - 3.81 MICROMETERS/150 MICROINCHES MINIMUM NICKEL OVER
 - COPPER UNDERPLATE OVERALL

SEE SHEET 1 EEC NO: UCP2013-1884 DRAWN BY: J. BARRA CHECKED BY: J. BARRA APPR: SMILLER DATE: 2012/11/12	QUALITY SYMBOLS	GENERAL TOLERANCES (UNLESS SPECIFIED)	DIMENSION STYLE	SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION
	▽=0	4 PLACES ±.010	MM/IN	2:1	METRIC	
	▽=0	3 PLACES ±.025				
	▽=0	2 PLACES ±.050				
		ANGULAR ±1/2°	DRAWN BY DATE	TITLE		
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	KSTILES 7/16/2003	PLATEAU HS DOCK 8.74 CL INTERPOSER SALES DRAWING		
			CHECKED BY DATE	DOCUMENT NO.		
			DSCHMIDG 7/16/2003	SD-75126-002		
			APPROVED BY DATE	SHEET NO.		
			MBANKIS 7/16/2003	2 OF 3		
			MATERIAL NO.	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		
			SEE TABLE			



DATE CODE, MOLEX, PART NUMBER



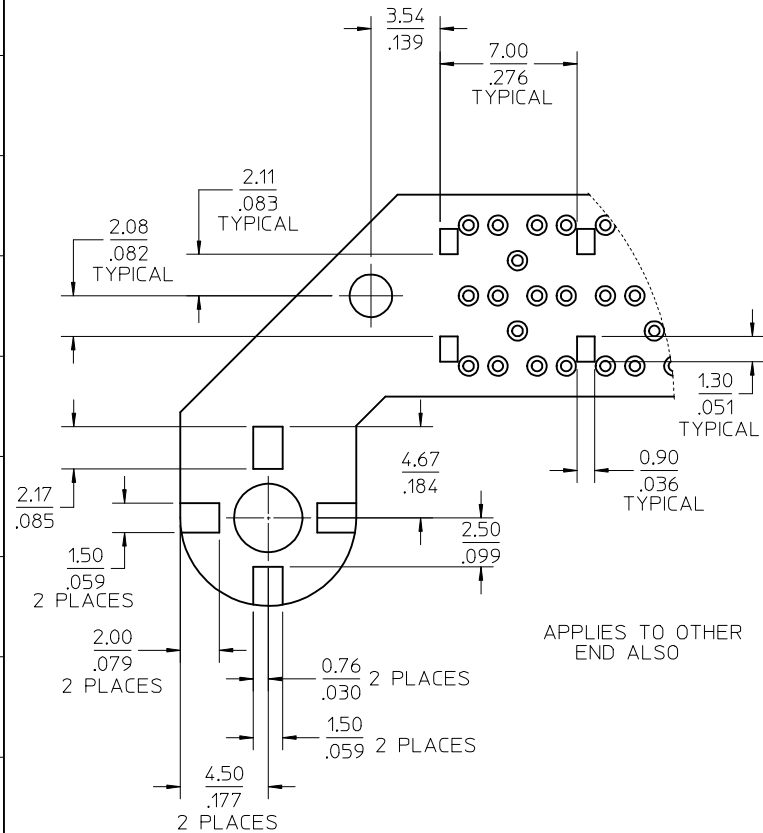
CIRCUIT SIZE	ITEM NUMBER	HS DOCK CONNECTOR	DIM 'A'	DIM 'B'	DIM 'C'	DIM 'D'	DIM 'E'	DIM 'F'	DIM 'G'	CONNECTOR WAFER TYPE
144	75126-7303	75018-5121	<u>111.50</u> 4.390	<u>102.50</u> 4.035	<u>110.00</u> 4.331	<u>96.62</u> 3.804	<u>120.40</u> 4.740	<u>92.00±0.08</u> 3.622±.003	<u>87.00±0.08</u> 3.425±.003	WELDLESS

NOTES:

- MATERIALS FOR INTERPOSER AND HIGH SPEED DOCKING CONNECTOR:
HOUSING: LIQUID CRYSTAL POLYMER (LCP), GLASS FILLED, 94V-0.
WAFER DIELECTRIC: LIQUID CRYSTAL POLYMER (LCP), 94V-0, BLACK.
CONTACTS: COPPER ALLOY
HEXAGONAL THREADED INSERT: CARBON STEEL
MACHINE SCREW: CARBON STEEL
- PLATING FINISH:
CONTACT INTERFACE
0.76 MICROMETERS/30 MICROINCHES MINIMUM SELECT GOLD
NICKEL UNDERPLATE OVERALL
COMPLIANT INTERFACE
0.76 MICROMETERS/30 MICROINCHES MINIMUM SELECT MATTE-TIN OVER
NICKEL UNDERPLATE OVERALL
HOUSING
3.81 MICROMETERS/150 MICROINCHES MINIMUM NICKEL OVER
COPPER UNDERPLATE OVERALL
- THIS ASSEMBLY CONFORMS TO PRODUCT SPECIFICATION PS-75018-001.
- THIS ASSEMBLY TO BE PACKAGED PER PK-75126-001.
- THIS ASSEMBLY CONFORMS TO CLASS C COSMETIC SPEC PS-45499-002.
- RECOMMENDED DRILL SIZE: 0.61±0.03 TO YIELD FINISHED PLATED THROUGH HOLE OF 0.55±0.05.
- USE APPLICATION TOOL 622020232 WHEN INSERTING INTO PCB.
- RECOMMENDED SCREW LENGTH TO MOUNT TO PCB TO BE 5mm, PLUS MOTHER BOARD THICKNESS MIN. TORQUE REQUIREMENT: 2 IN-LBS MIN, 5 IN-LBS MAX.

INITIAL RELEASE EC NO: UCP2014-3379 DRAWN BY: IBARRA 2014/02/13 CHKD BY: BARKER 2014/02/14 APPR: SMILLER 2014/03/13	QUALITY SYMBOLS	GENERAL TOLERANCES (UNLESS SPECIFIED)	DIMENSION STYLE	SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION
	▽=0	mm INCH	MM/IN	2:1	METRIC	
	▽=0	4 PLACES ± --- ± ---				
	▽=0	3 PLACES ± --- ± .010				
		2 PLACES ± 0.25 ± ---				
		1 PLACE ± --- ± ---				
		0 PLACE ± ±				
		ANGULAR ± 2 °				
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS				
			MATERIAL NO.	DOCUMENT NO.		
			SEE TABLE	SD-75126-1000		
						SHEET NO. 1 OF 2
			THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			

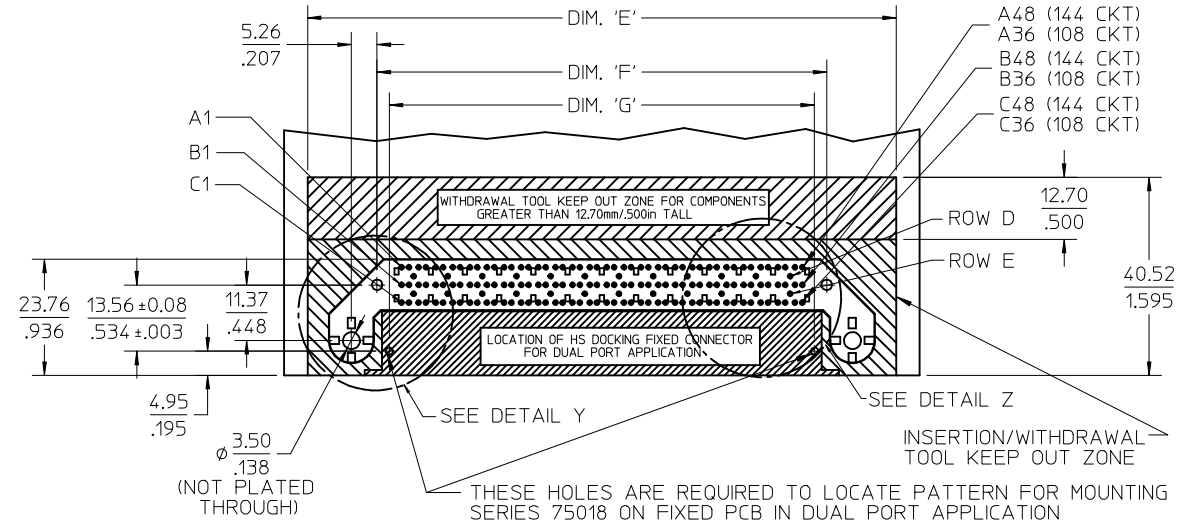
KEEP OUT AREA FOR CONNECTOR STAND-OFFS



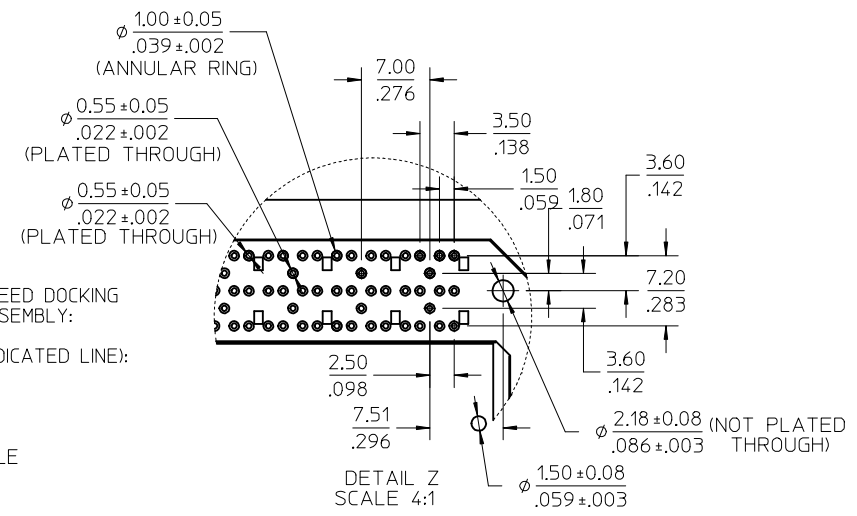
DETAIL Y
SCALE 8:1

NOTE: THE DIMENSION DEFINING THE LOCATION AND SIZE OF THE KEEP OUT AREAS DO NOT HAVE TOLERANCES. AT A MINIMUM THE POWER PLANE MUST NOT COME INSIDE THE AREAS DEFINED BY THESE DIMENSIONS.

APPLIES TO OTHER END ALSO



THESE HOLES ARE REQUIRED TO LOCATE PATTERN FOR MOUNTING SERIES 75018 ON FIXED PCB IN DUAL PORT APPLICATION



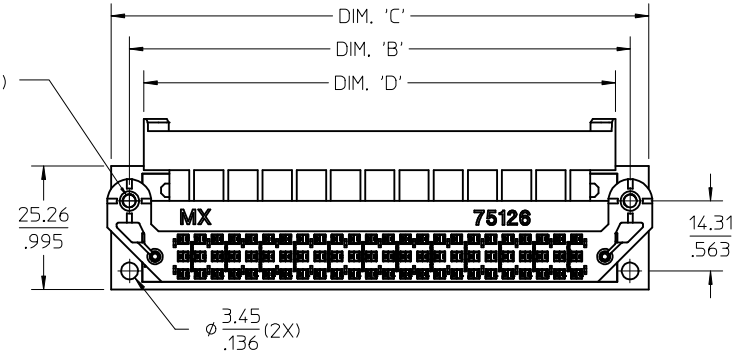
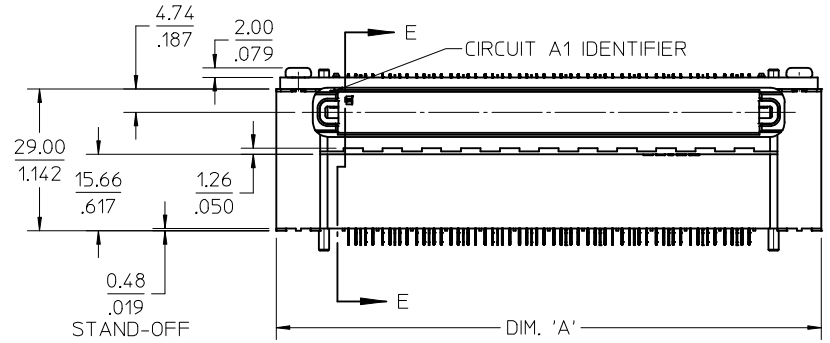
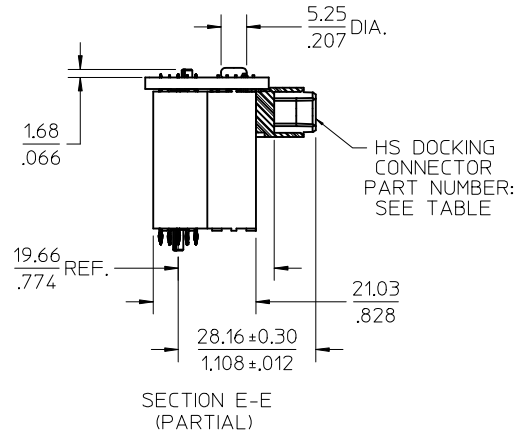
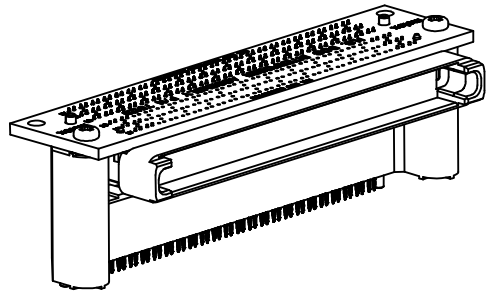
DETAIL Z
SCALE 4:1

CIRCUIT DESIGNATION FOR HIGH SPEED DOCKING INTERPOSER CONNECTOR ASSEMBLY:
 A2-A1: POWER/RETURN;
 A4-A3: POWER/RETURN;
 C2-C1: POWER/RETURN

ALL REMAINING ROWS ARE SUITABLE FOR DIFFERENTIAL PAIRS
 CURRENT CAPACITY: 300mA

GROUND CIRCUITS: ROWS D & E

SEE SHEET 1 IEC NO: UCP2014-3379 DRAWN BY: TIBARRA 2014/02/13 CHECKED BY: CHYKOBARKER 2014/02/14 APPROVED BY: SMILLER 2014/03/13	QUALITY SYMBOLS	GENERAL TOLERANCES (UNLESS SPECIFIED)	DIMENSION STYLE	SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION
	▽=0	mm INCH	MM/IN	1:1	METRIC	☉
	▽=0	4 PLACES ± --- ± ---	DRAWN BY DATE	TITLE		
	▽=0	3 PLACES ± --- ± .010	TIBARRA 2014/02/13	PLATEAU HS DOCK INTERPOSER SALES DRAWING		
	2 PLACES ± 0.25 ± ---	CHECKED BY DATE	DOCUMENT NO.			SHEET NO.
	1 PLACE ± --- ± ---	BBARKER 2014/02/14	SD-75126-1000			2 OF 2
	0 PLACE ± --- ± ---	APPROVED BY DATE	MATERIAL NO.			
		SMILLER 2014/03/13	SEE TABLE			
			DRAFT WHERE APPLICABLE			
			MUST REMAIN WITHIN DIMENSIONS			
			SIZE D			
			THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			



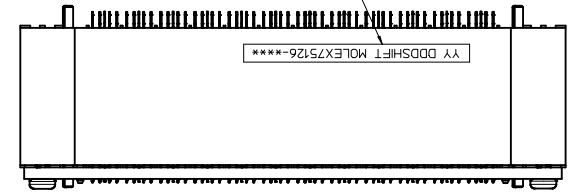
M3x0.5 THREADED INSERT (2X)

CIRCUIT SIZE	ITEM NUMBER	HS DOCK CONNECTOR	DIM 'A'	DIM 'B'	DIM 'C'	DIM 'D'	DIM 'E'	DIM 'F'	DIM 'G'	CONNECTOR WAFER TYPE
144	75126-7303	75018-5121	<u>111.50</u> 4.390	<u>102.50</u> 4.035	<u>110.00</u> 4.331	<u>96.62</u> 3.804	<u>120.40</u> 4.740	<u>92.00±0.08</u> 3.622±.003	<u>87.00±0.08</u> 3.425±.003	WELDLESS

NOTES:

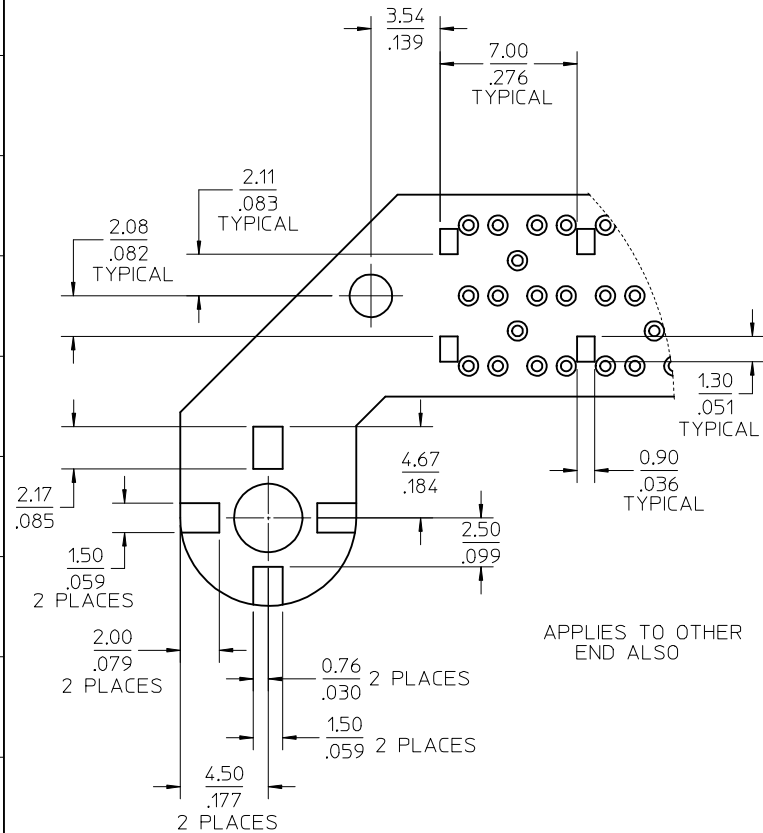
- MATERIALS FOR INTERPOSER AND HIGH SPEED DOCKING CONNECTOR:
HOUSING: LIQUID CRYSTAL POLYMER (LCP), GLASS FILLED, 94V-0.
WAFER DIELECTRIC: LIQUID CRYSTAL POLYMER (LCP), 94V-0, BLACK.
CONTACTS: COPPER ALLOY
HEXAGONAL THREADED INSERT: CARBON STEEL
MACHINE SCREW: CARBON STEEL
- PLATING FINISH:
CONTACT INTERFACE
0.76 MICROMETERS/30 MICROINCHES MINIMUM SELECT GOLD
NICKEL UNDERPLATE OVERALL
COMPLIANT INTERFACE
0.76 MICROMETERS/30 MICROINCHES MINIMUM SELECT MATTE-TIN OVER
NICKEL UNDERPLATE OVERALL
HOUSING
3.81 MICROMETERS/150 MICROINCHES MINIMUM NICKEL OVER
COPPER UNDERPLATE OVERALL
- THIS ASSEMBLY CONFORMS TO PRODUCT SPECIFICATION PS-75018-001.
- THIS ASSEMBLY TO BE PACKAGED PER PK-75126-001.
- THIS ASSEMBLY CONFORMS TO CLASS C COSMETIC SPEC PS-45499-002.
- RECOMMENDED DRILL SIZE: 0.61±0.03 TO YIELD FINISHED PLATED THROUGH HOLE OF 0.55±0.05.
- USE APPLICATION TOOL 622020232 WHEN INSERTING INTO PCB.
- RECOMMENDED SCREW LENGTH TO MOUNT TO PCB TO BE 5mm, PLUS MOTHER BOARD THICKNESS MIN. TORQUE REQUIREMENT: 2 IN-LBS MIN, 5 IN-LBS MAX.

DATE CODE, MOLEX, PART NUMBER



INITIAL RELEASE EC NO: UCP2014-3379 DRAWN BY: TIBARRA 2014/02/13 CHECKED BY: CHYD BARKER 2014/02/14 APPROVED BY: SMILLER 2014/03/13	QUALITY SYMBOLS ∇=0 ∇=0 ∇=0	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM/IN	SCALE 2:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
		4 PLACES ± --- ± --- 3 PLACES ± --- ± .010 2 PLACES ± 0.25 ± --- 1 PLACE ± --- ± --- 0 PLACE ± --- ± ---	mm INCH	DRAWN BY: TIBARRA DATE: 2014/02/13 CHECKED BY: BARKER DATE: 2014/02/14 APPROVED BY: SMILLER DATE: 2014/03/13	TITLE PLATEAU HS DOCK INTERPOSER SALES DRAWING		
		ANGULAR ± 2 ° DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		MATERIAL NO. SEE TABLE	DOCUMENT NO. SD-75126-1000	SHEET NO. 1 OF 2	
		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION					

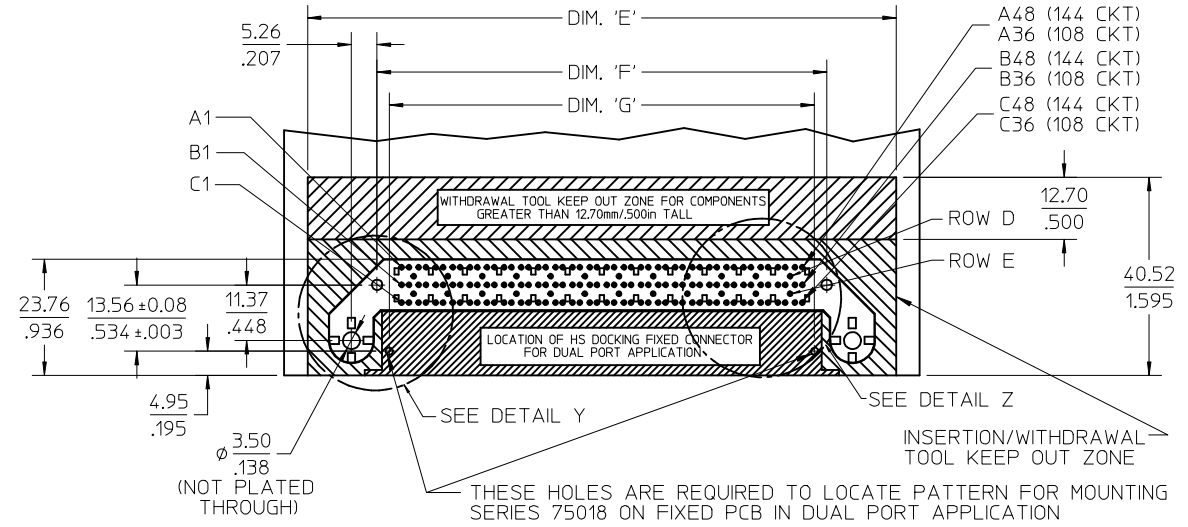
KEEP OUT AREA FOR CONNECTOR STAND-OFFS



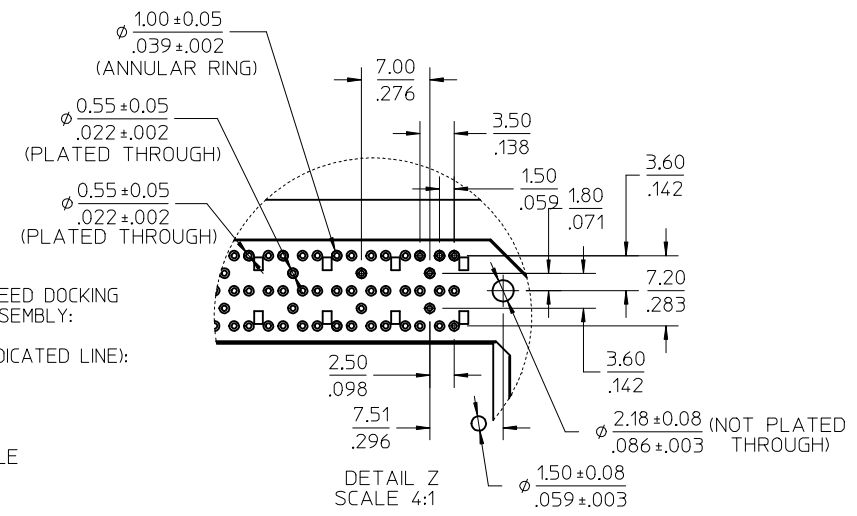
DETAIL Y
SCALE 8:1

NOTE: THE DIMENSION DEFINING THE LOCATION AND SIZE OF THE KEEP OUT AREAS DO NOT HAVE TOLERANCES. AT A MINIMUM THE POWER PLANE MUST NOT COME INSIDE THE AREAS DEFINED BY THESE DIMENSIONS.

APPLIES TO OTHER END ALSO



THESE HOLES ARE REQUIRED TO LOCATE PATTERN FOR MOUNTING SERIES 75018 ON FIXED PCB IN DUAL PORT APPLICATION



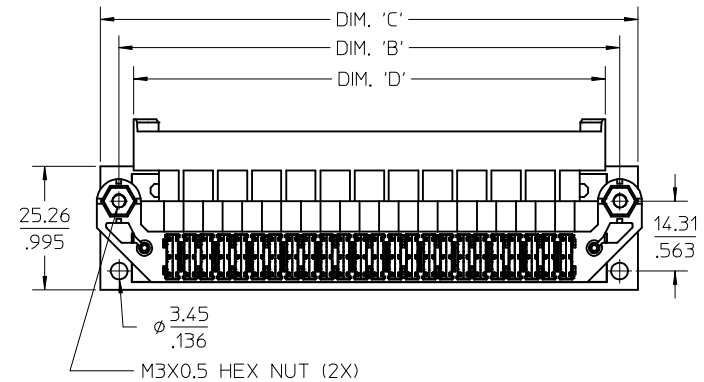
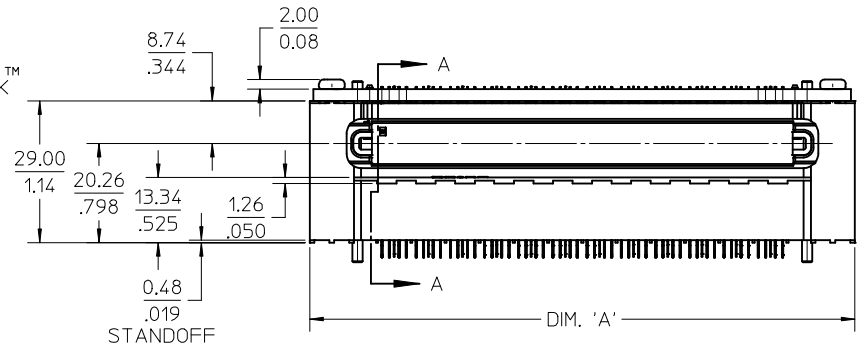
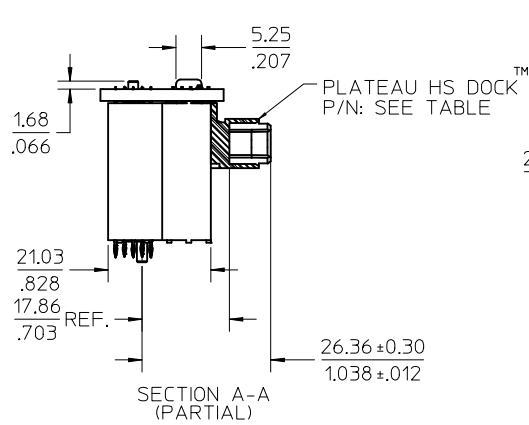
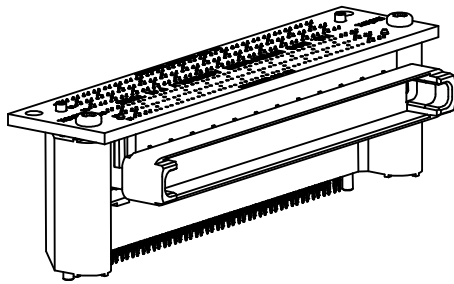
DETAIL Z
SCALE 4:1

CIRCUIT DESIGNATION FOR HIGH SPEED DOCKING INTERPOSER CONNECTOR ASSEMBLY:
 A2-A1: POWER/RETURN;
 A4-A3: POWER/RETURN;
 C2-C1: POWER/RETURN

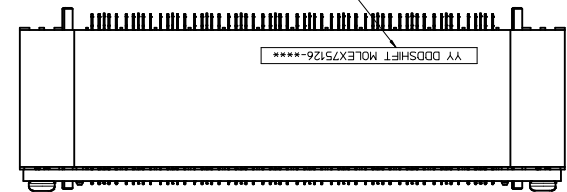
ALL REMAINING ROWS ARE SUITABLE FOR DIFFERENTIAL PAIRS
 CURRENT CAPACITY: 300mA

GROUND CIRCUITS: ROWS D & E

SEE SHEET 1 IEC NO: UCP2014-3379 DRAWN BY: TIBARRA 2014/02/13 CHECKED BY: CHYKOBARKER 2014/02/14 APPROVED BY: SMILLER 2014/03/13	QUALITY SYMBOLS	GENERAL TOLERANCES (UNLESS SPECIFIED)	DIMENSION STYLE	SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION	
	▽=0	mm INCH	MM/IN	1:1	METRIC	☉	
	▽=0	4 PLACES ± --- ± ---	DRAWN BY DATE	TIBARRA 2014/02/13	TITLE		PLATEAU HS DOCK INTERPOSER SALES DRAWING
	▽=0	3 PLACES ± --- ± .010	CHECKED BY DATE	BBARKER 2014/02/14	DOCUMENT NO.		SD-75126-1000
	1 PLACE ± --- ± ---	APPROVED BY DATE	SMILLER 2014/03/13	SHEET NO.		2 OF 2	
	0 PLACE ± --- ± ---			MATERIAL NO.		SEE TABLE	
		ANGULAR ± 2 °		DRAFT WHERE APPLICABLE		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION	



DATE CODE, MOLEX, PART NUMBER



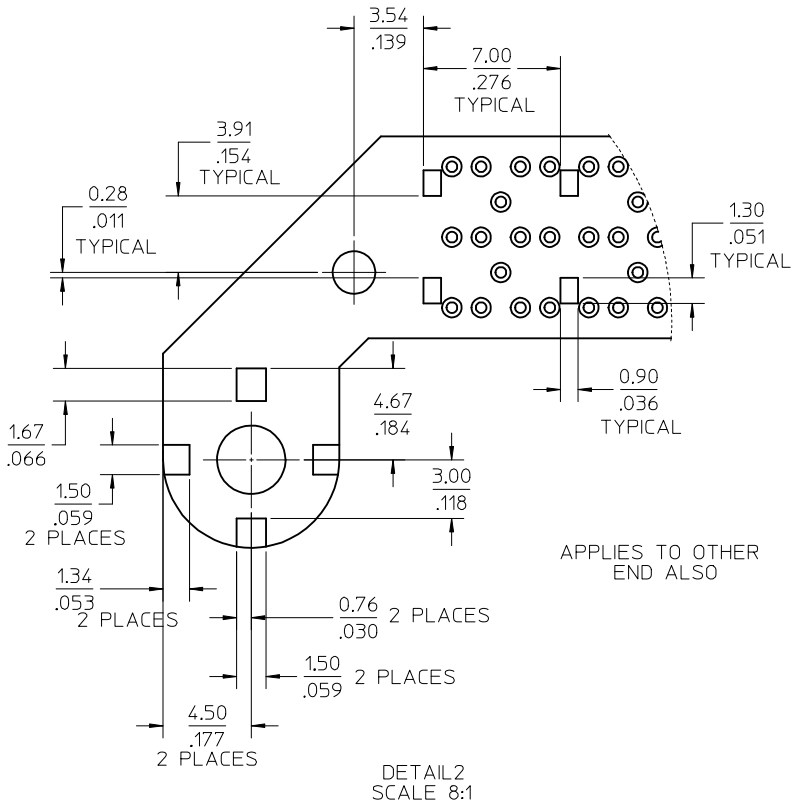
CIRCUIT SIZE	ITEM NUMBER	PLATEAU HS DOCK™	DIM 'A'	DIM 'B'	DIM 'C'	DIM 'D'	DIM 'E'	DIM 'F'	DIM 'G'	CONNECTOR WAFER TYPE
144	75126-8301	75018-5123	111.50 / 4.390	102.50 / 4.035	110.00 / 4.331	96.62 / 3.804	120.40 / 4.740	92.00±0.08 / 3.622±.003	87.00±0.08 / 3.425±.003	WELDLESS

NOTES:

- MATERIALS FOR INTERPOSER AND HIGH SPEED DOCKING CONNECTOR:
 HOUSING: LIQUID CRYSTAL POLYMER (LCP), GLASS FILLED, 94 V-0.
 WAFER: LIQUID CRYSTAL POLYMER (LCP), 94 V-0, BLACK.
 CONTACTS: COPPER ALLOY
 HEXAGONAL THREADED INSERT: CARBON STEEL
 MACHINE SCREW: CARBON STEEL
- PLATING FINISH:
 CONTACT INTERFACE
 0.76 MICROMETERS/30 MICROINCHES MINIMUM SELECT GOLD
 NICKEL UNDERPLATE OVERALL
 COMPLIANT INTERFACE
 0.76 MICROMETERS/30 MICROINCHES MINIMUM SELECT MATTE-TIN OVER
 NICKEL UNDERPLATE OVERALL
 HOUSING
 3.81 MICROMETERS/150 MICROINCHES MINIMUM NICKEL OVER
 COPPER UNDERPLATE OVERALL
- THIS ASSEMBLY CONFORMS TO PRODUCT SPECIFICATION PS-75018-001.
- THIS ASSEMBLY TO BE PACKAGED PER PK-75126-001.
- THIS ASSEMBLY CONFORMS TO CLASS C COSMETIC SPEC. PS-45499-002.
- RECOMMENDED DRILL SIZE: 0.66±0.03 TO YIELD FINISHED PLATED THROUGH HOLE OF 0.55±0.05.
- USE APPLICATION TOOL 62202XXXX WHEN INSERTING INTO PCB.
- RECOMMENDED SCREW LENGTH TO MOUNT TO PCB TO BE 5mm, PLUS MOTHER BOARD THCKNESS MIN.
 TORQUE REQUIREMENT: 2 IN-LBS MIN. 5 IN-LBS MAX.

INITIAL RELEASE EC NO: UCP2014-3379 DRAWN BY: TIBARRA 2014/02/13 CHKD BY: BARKER 2014/02/14 APPR: SMILLER 2014/03/13	QUALITY SYMBOLS	GENERAL TOLERANCES (UNLESS SPECIFIED)	DIMENSION STYLE	SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION
	▽=0	mm	MM/IN	2:1	METRIC	☉
	▽=0	INCH				
	▽=0	4 PLACES ±.010 3 PLACES ±.025 2 PLACES ±.050 1 PLACE ±.100 0 PLACE ±.150				
	ANGULAR ±1/2°	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	MATERIAL NO.	DOCUMENT NO.	SHEET NO.	
	SIZE D	SEE TABLE	SD-75126-2000	1 OF 2		
THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION						

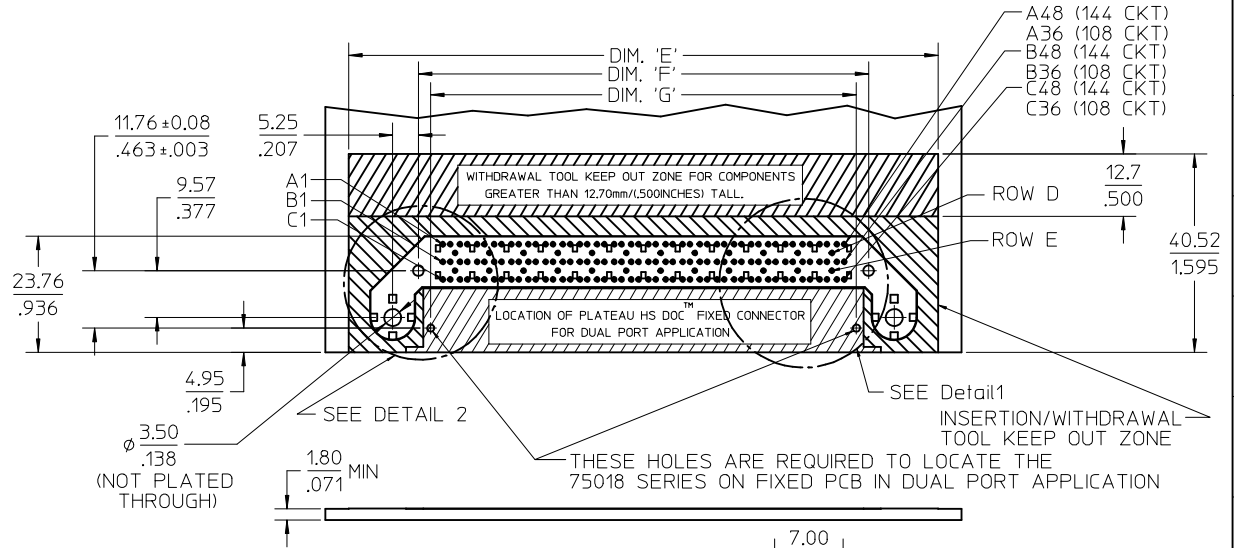
KEEP OUT AREA FOR STAND-OFFS



DETAIL2
SCALE 8:1

NOTE: THE DIMENSIONS DEFINING THE LOCATION AND SIZE OF THE KEEP OUT AREAS DO NOT HAVE TOLERANCES. AT A MINIMUM THE POWER PLANE MUST NOT COME INSIDE THE AREAS DEFINED BY THESE DIMENSIONS.

APPLIES TO OTHER END ALSO

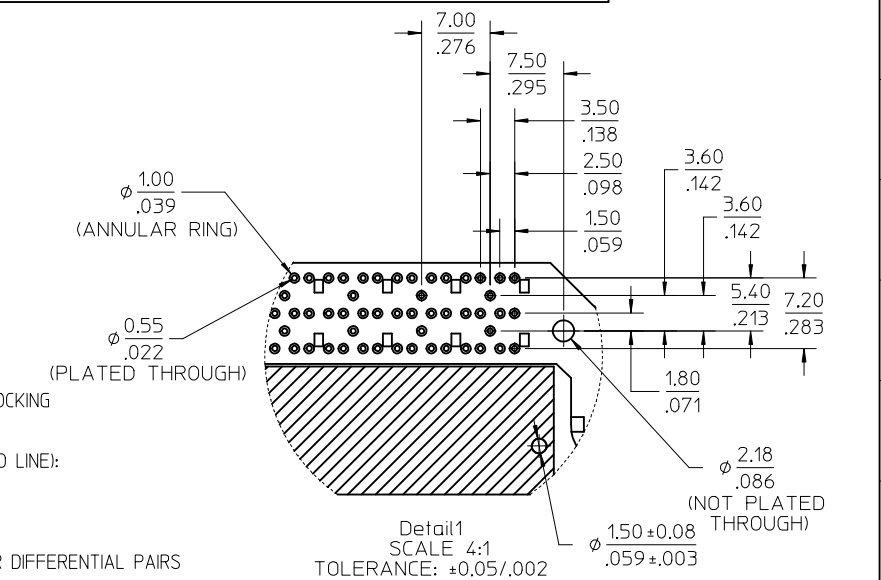


CIRCUIT DESIGNATION FOR HIGH SPEED DOCKING INTERPOSER CONNECTOR ASSEMBLY:

POWER CIRCUITS (15 AMPS PER INDICATED LINE):
A2-A1: POWER/RETURN,
A4-A3: POWER/RETURN,
C2-C1: POWER/RETURN

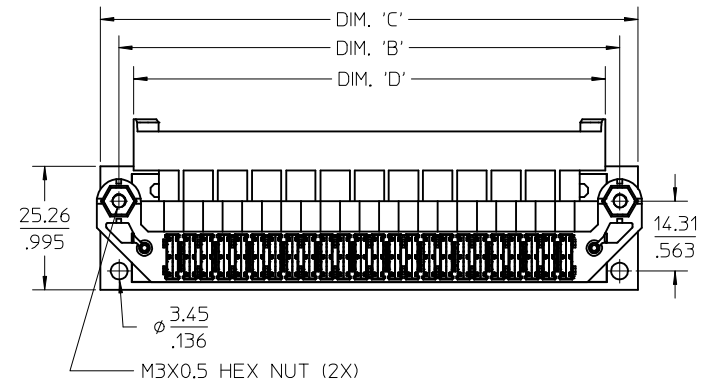
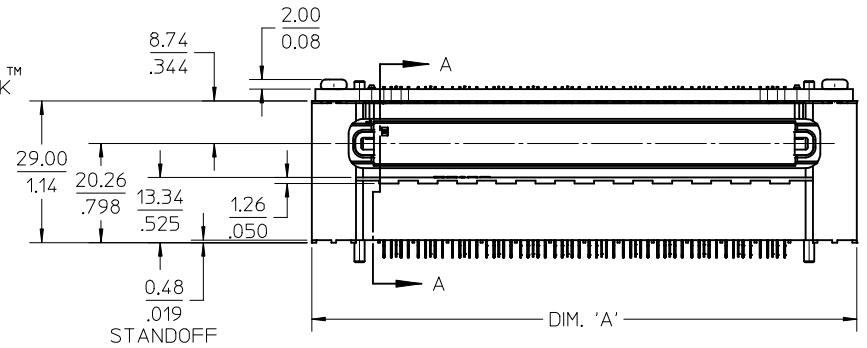
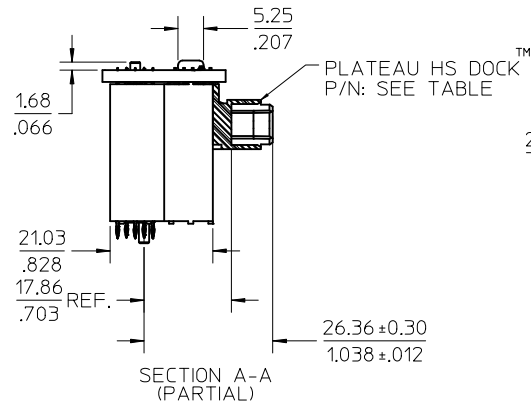
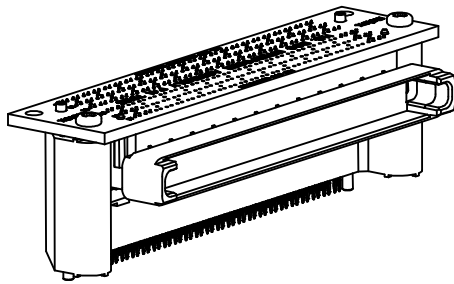
ALL REMAINING ROWS ARE SUITABLE FOR DIFFERENTIAL PAIRS
CURRENT CAPACITY: 300mA

GROUND CIRCUITS: ROWS D & E

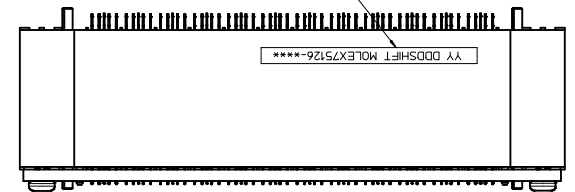


Detail1
SCALE 4:1
TOLERANCE: ±0.05/1.002

SEE SHEET 1 IEC NO: UCP2014-3379 DRAWN BY: T1BARRA 2014/02/13 CHECKED BY: BBARKER 2014/02/14 APPROVED BY: SMILLER 2014/03/13	QUALITY SYMBOLS	GENERAL TOLERANCES (UNLESS SPECIFIED)	DIMENSION STYLE	SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION
	▽=0	mm INCH	MM/IN	2:1	METRIC	☉
	▽=0	4 PLACES ± .010	DATE	DATE	PLATEAU HS DOCK 8.74 CL INTERPOSER SALES DRAWING	
	▽=0	3 PLACES ± 0.25	DATE	DATE	moxle SD-75126-2000	
	1 PLACE ± .010	DATE	DATE	DOCUMENT NO.	SHEET NO.	
	0 PLACE ± .010	DATE	DATE	SEE TABLE	2 OF 2	
	ANGULAR ±1/2°	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			



DATE CODE, MOLEX, PART NUMBER



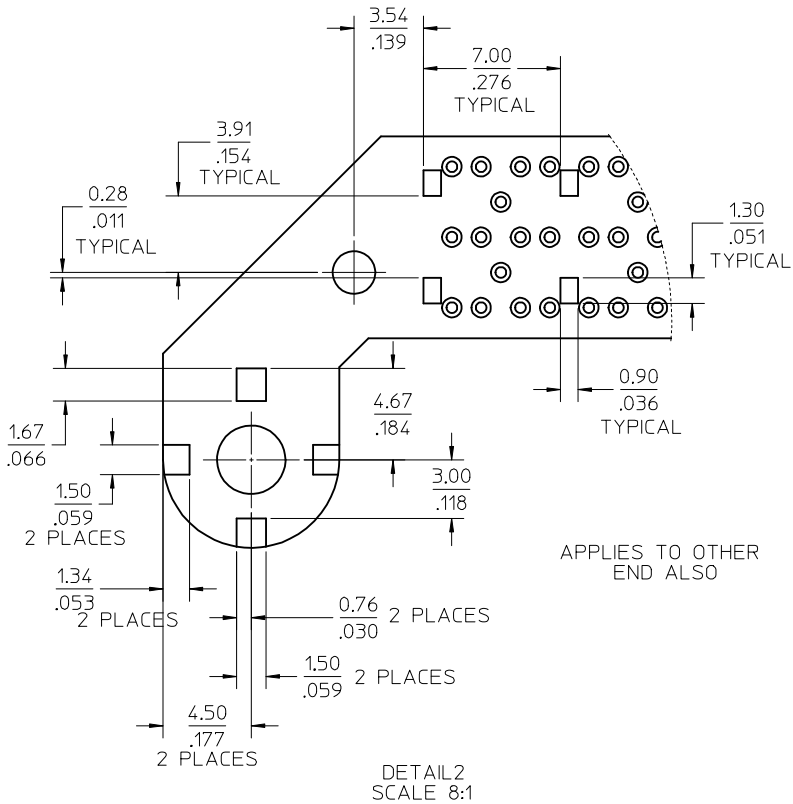
CIRCUIT SIZE	ITEM NUMBER	PLATEAU HS DOCK™	DIM 'A'	DIM 'B'	DIM 'C'	DIM 'D'	DIM 'E'	DIM 'F'	DIM 'G'	CONNECTOR WAFER TYPE
144	75126-8301	75018-5123	111.50 / 4.390	102.50 / 4.035	110.00 / 4.331	96.62 / 3.804	120.40 / 4.740	92.00±0.08 / 3.622±.003	87.00±0.08 / 3.425±.003	WELDLESS

NOTES:

- MATERIALS FOR INTERPOSER AND HIGH SPEED DOCKING CONNECTOR:
 HOUSING: LIQUID CRYSTAL POLYMER (LCP), GLASS FILLED, 94 V-0.
 WAFER: LIQUID CRYSTAL POLYMER (LCP), 94 V-0, BLACK.
 CONTACTS: COPPER ALLOY
 HEXAGONAL THREADED INSERT: CARBON STEEL
 MACHINE SCREW: CARBON STEEL
- PLATING FINISH:
 CONTACT INTERFACE
 0.76 MICROMETERS/30 MICROINCHES MINIMUM SELECT GOLD
 NICKEL UNDERPLATE OVERALL
 COMPLIANT INTERFACE
 0.76 MICROMETERS/30 MICROINCHES MINIMUM SELECT MATTE-TIN OVER
 NICKEL UNDERPLATE OVERALL
 HOUSING
 3.81 MICROMETERS/150 MICROINCHES MINIMUM NICKEL OVER
 COPPER UNDERPLATE OVERALL
- THIS ASSEMBLY CONFORMS TO PRODUCT SPECIFICATION PS-75018-001.
- THIS ASSEMBLY TO BE PACKAGED PER PK-75126-001.
- THIS ASSEMBLY CONFORMS TO CLASS C COSMETIC SPEC. PS-45499-002.
- RECOMMENDED DRILL SIZE: 0.66±0.03 TO YIELD FINISHED PLATED THROUGH HOLE OF 0.55±0.05.
- USE APPLICATION TOOL 62202XXXX WHEN INSERTING INTO PCB.
- RECOMMENDED SCREW LENGTH TO MOUNT TO PCB TO BE 5mm, PLUS MOTHER BOARD THCKNESS MIN.
 TORQUE REQUIREMENT: 2 IN-LBS MIN. 5 IN-LBS MAX.

INITIAL RELEASE EC NO: UCP2014-3379 DRAWN BY: TIBARRA 2014/02/13 CHECKED BY: CHYKOBARKER 2014/02/14 APPR. MILLER 2014/03/13	QUALITY SYMBOLS ∇=0 ∇=0 ∇=0	GENERAL TOLERANCES (UNLESS SPECIFIED): mm INCH 4 PLACES ±.--- ±.--- 3 PLACES ±.--- ±.010 2 PLACES ±.025 ±.--- 1 PLACE ±.--- ±.--- 0 PLACE ±.--- ±.---	DIMENSION STYLE MM/IN	SCALE 2:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION		
		DRAWN BY: TIBARRA 2014/02/13 CHECKED BY: BARKER 2014/02/14 APPROVED BY: SMILLER 2014/03/13	MATERIAL NO. SEE TABLE	DOCUMENT NO. SD-75126-2000	SHEET NO. 1 OF 2			
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS				TITLE PLATEAU HS DOCK 8.74 CL INTERPOSER SALES DRAWING		
		ANGULAR ±1/2° SIZE D THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION				molex		

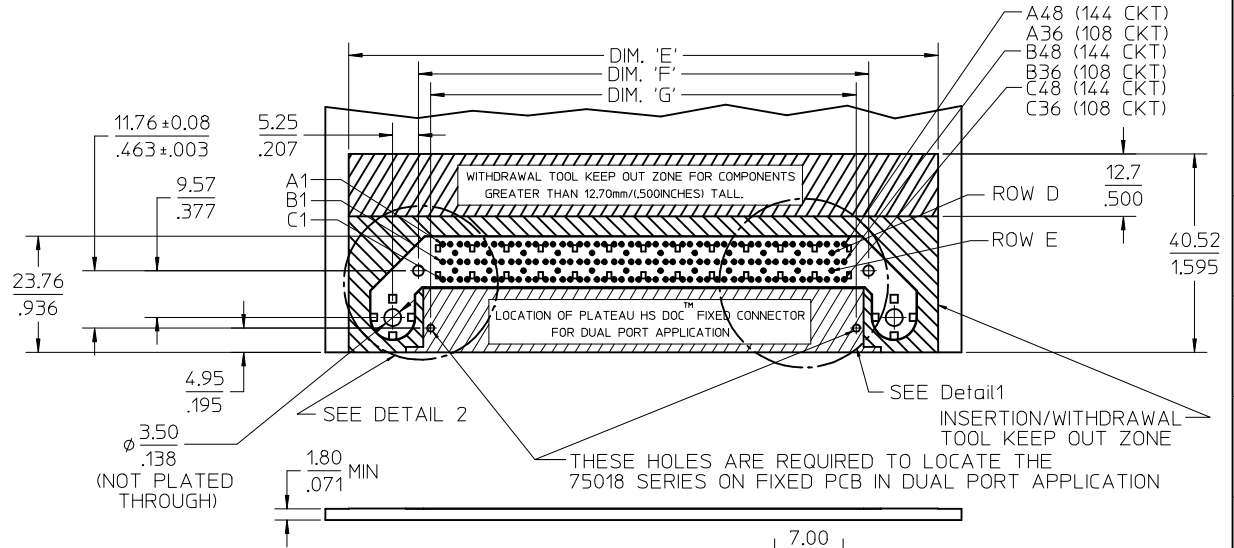
KEEP OUT AREA FOR STAND-OFFS



DETAIL2
SCALE 8:1

NOTE: THE DIMENSIONS DEFINING THE LOCATION AND SIZE OF THE KEEP OUT AREAS DO NOT HAVE TOLERANCES. AT A MINIMUM THE POWER PLANE MUST NOT COME INSIDE THE AREAS DEFINED BY THESE DIMENSIONS.

APPLIES TO OTHER END ALSO



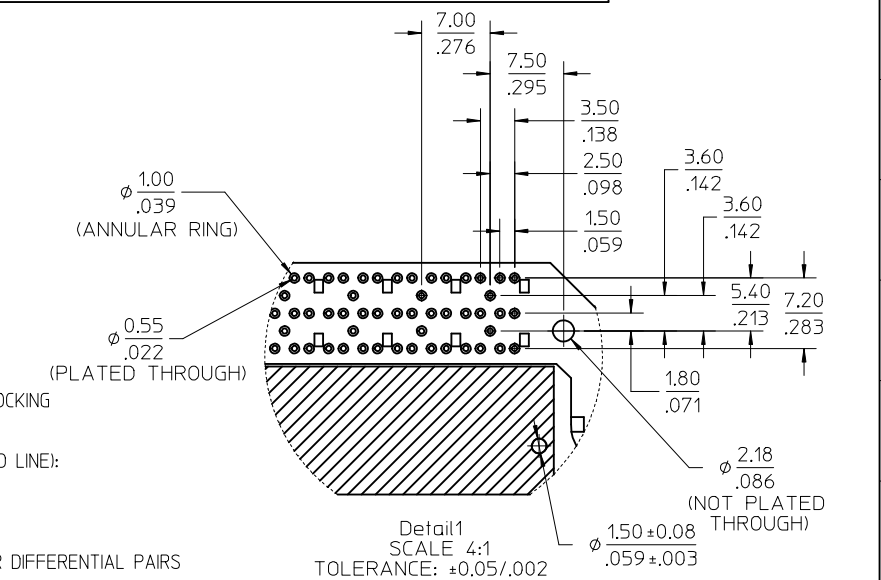
THESE HOLES ARE REQUIRED TO LOCATE THE 75018 SERIES ON FIXED PCB IN DUAL PORT APPLICATION

CIRCUIT DESIGNATION FOR HIGH SPEED DOCKING INTERPOSER CONNECTOR ASSEMBLY:

POWER CIRCUITS (15 AMPS PER INDICATED LINE):
A2-A1: POWER/RETURN,
A4-A3: POWER/RETURN,
C2-C1: POWER/RETURN

ALL REMAINING ROWS ARE SUITABLE FOR DIFFERENTIAL PAIRS
CURRENT CAPACITY: 300mA

GROUND CIRCUITS: ROWS D & E



Detail1
SCALE 4:1

TOLERANCE: ±0.05/±.002

SEE SHEET 1 IEC NO: UCP2014-3379 DRAWN BY: T1BARRA 2014/02/13 CHECKED BY: BBARKER 2014/02/14 APPROVED BY: SMILLER 2014/03/13	QUALITY SYMBOLS	GENERAL TOLERANCES (UNLESS SPECIFIED)	DIMENSION STYLE	SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION
	▽=0	mm INCH	MM/IN	2:1	METRIC	☉
	▽=0	4 PLACES ± .010	DATE	DATE	TITLE	
	▽=0	3 PLACES ± .025	2014/02/13	2014/02/14	PLATEAU HS DOCK 8.74 CL INTERPOSER SALES DRAWING	
	1 PLACE ± .010	APPROVED BY: SMILLER 2014/03/13				
	0 PLACE ± .010					
	ANGULAR ±1/2°					
	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS					
		MATERIAL NO.	DOCUMENT NO.			
		SEE TABLE	SD-75126-2000			
		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION				

PLATEAU HS DOCK
8.74 CL INTERPOSER
SALES DRAWING

molex

SD-75126-2000

SHEET NO.
2 OF 2